

BREMEN-D

CPU : AMD Caspin
Chip Set : AMD RX881 + SB710
Remarks : Tigris Platform
Park-XT M2

Model Name : Bremen-D
PBA Name : MAIN
PCB Code : GCE :
NAN :
HAN :
Dev. Step : PV
Revision : 1.4
T.R. Date : 2009.11.10

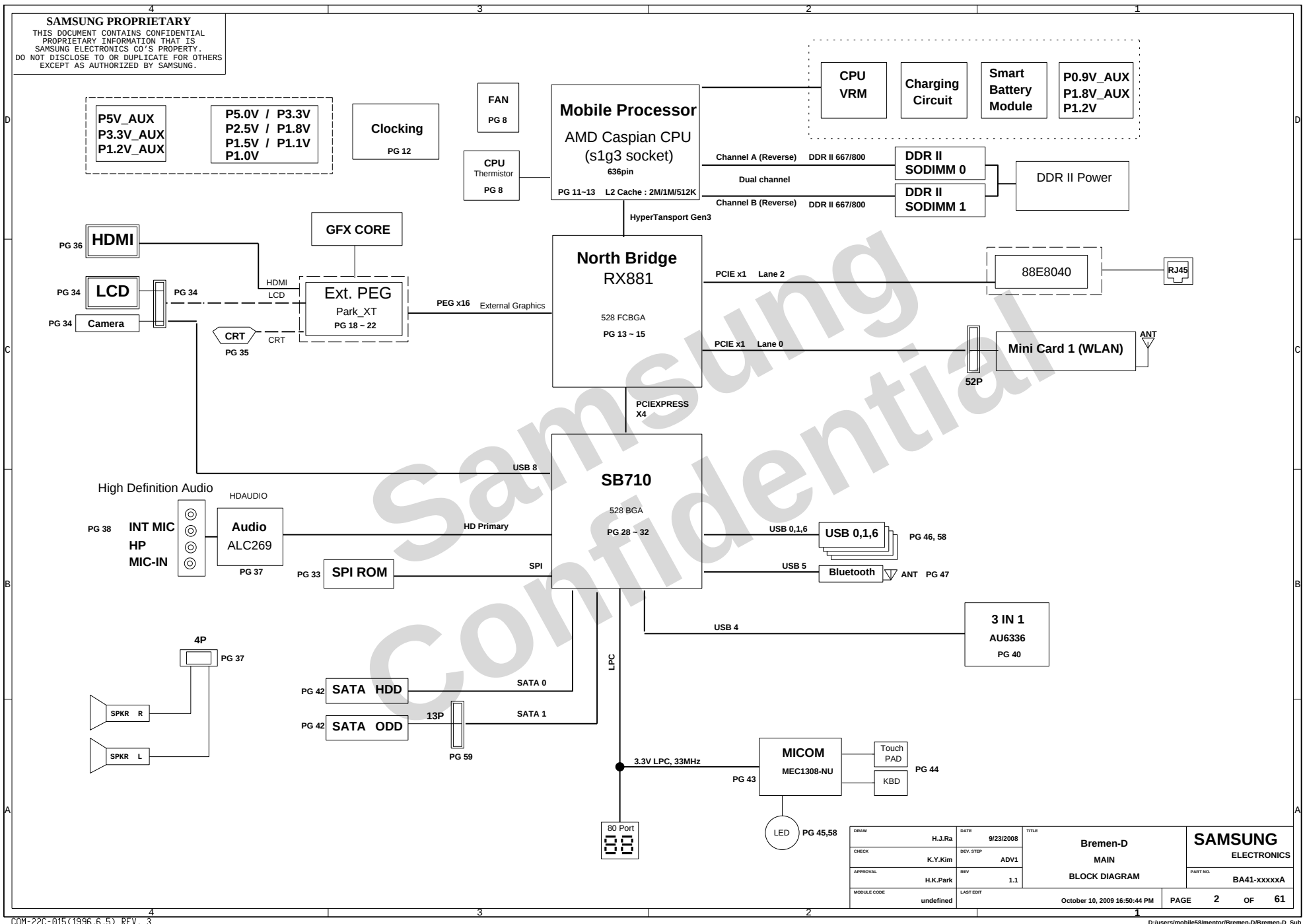
Design	CHECK	APPROVAL

Owner : SEC Mobile R & D Signature : X

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DRAW	XIE, BIN	DATE	10/10/2008	TITLE	Bremen-D	SAMSUNG
CHECK	GUO, LEI	DEV. STEP	PV	MAIN		ELECTRONICS
APPROVAL	LEE, BC	REV	1.0	COVER	PART NO.	BA41-xxxxxA
MODULE CODE	LAST EDIT			October, 28, 2009 11:35:37 AM	PAGE	1 OF



BOARD INFORMATION

SCHEMATIC ANNOTATIONS AND BOARD INFORMATION

Voltage Rails

VDC	Primary DC system power supply (7 to 21V)
CPU_CORE	Core Voltage for CPU
EGFX_CORE	Core Voltage for GPU
P1.1V	VTT for RX881
P1.2V	Core Voltage for SB710, CPU_VDLT, RX881
P3.3V_MICOM	3.3V always power rail (for Micom)
P1.5V	1.5V switched power rail (off in S3-S5)
P1.8V	1.8V switched power rail (off in S3-S5)
P1.8V_AUX	1.8V power rail for DDR (off in S4-S5)
P1.0V	0.9V power rail for DDR (off in S3-S5)
P2.5V	2.5V switched power rail (off in S3-S5)
P3.3V	3.3V switched power rail (off in S3-S5)
P3.3V_AUX	3.3V switched on power rail (off in S4-S5)
P5.0V	5.0V switched power rail (off in S3-S5)
P5.0V_AUX	5.0V switched on power rail (off in S4-S5)
P5.0V_STB	5.0V always power rail
P12.0V_ALW	12.0V always power rail

Crystal / Oscillator

TYPE	FREQUENCY	DEVICE	USAGE
Crystal	32.768KHz	SB710	Real Time Clock
Crystal	10MHz	MICOM	MEC1308-NU
Crystal	14.313MHz	CLOCK-Generator	CK-505
Crystal	25MHz	LAN	88E8040
Crystal	25MHz	SATA	SB710

I²C / SMB Address

Devices	Address	Hex	Bus
S710	Master	-	SMBUS Master
CPU Thermal Sensor	0111 101x	7Ah	Thermal Sensor
SODIMM0	1010 000x	A0h	-
SODIMM1	1010 010x	A4h	-
Thermal Sensor on SODIMM0	0011 000x	30h	-
Thermal Sensor on SODIMM1	0011 010x	34h	-
CK-505M (Clock Generator)	1101 0010	D2h	Clock, Unused Clock Output Disable
Gfx (DTS)		41h	Gfx Thermal SMBUS Slave ID

USB PORT Assign

PORT #	ASSIGNED TO
0	SYSTEM PORT 0
1	SYSTEM PORT 1
2	NC
3	NC
4	3 IN 1
5	Bluetooth
6	SYSTEM PORT 2
7	NC
8	Camera
9	NC
10	NC

PCI Express Assign

PORT #	ASSIGNED TO
0	Mini Card (WLAN)
1	NC
2	LOM
3	NC
4	NC
5	NC

LCD Pannel Detect (TBD)

Devices	Resolution	PANNEL_DETECT_0(strap0)
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REVISION HISTORY

See rev notes for more information.

DRAW	H.J.Ra	DATE	08/18/2009	TITLE	Bremen-D	SAMSUNG
CHECK	K.Y.Kim	DEV. STEP	ADV1	MAIN	MAIN	ELECTRONICS
APPROVAL	H.K.Park	REV	1.1	BOARD INFORMATION	PART NO.	BA41-xxxxxA
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POWER DIAGRAM

Rev 0.3

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AC Adapter

Battery DC

VDC

KBC3_SUSPWR
(CHP3_S4_STATE*)

KBC3_PWRON
(CHP3_SLPS3*)

KBC3_VRON

P5V_AUX

USB connector

P1.8V_AUX

AMD S1G3
SODIMM (DDR II)

P0.9V_AUX

DDR II-Termination

P1.2V_AUX

SB710

P3.3V_AUX

SB710
WLAN
LAN
THERMAL
LVDS
LED

P1.2V_LAN

LAN

P3.3V_MICOM

MICOM LED SB710

P5.0V_STB

USB N Charger

P12.0V_ALW

P1.8V

RX881
Park-XT M2 / Madison-LP
gDDR-3 for EGfx
AU6336

P5.0V

THERMAL CRT HDMI
SB710 MICOM AUDIO
ODD HDD CAMERA
TOUCH PAD

EGFX_CORE

Park-XT M2 / Madison-LP

P1.5V

CK505
WLAN
EXPRESS CARD

P1.0V

Park-XT M2 / Madison-LP

P2.5V

S1G3

P3.3V

CK505 THERMAL RX881
DDR2 CRT PARK / MADISON
LVDS HDMI SB710
SPI WLAN LEDS
LAN AUDIO AU6336
HDD BT

CPU_CORE

S1G3

P1.2V

S1G3
RX881
SB710

P1.1V

RX881
Park-XT M2
Madison-LP

Power On/Off Table by S-state

Rail State	S0	S3	S4	S5
+V*A(LWS) +V*LAN	ON	ON	ON	ON
+1.8V_AUX +0.9V_AUX	ON	ON	—	—
+V*AUX	ON	ON	—	—
+V	ON	—	—	—
+V* (CORE)	ON	—	—	—

S5-S4

S3

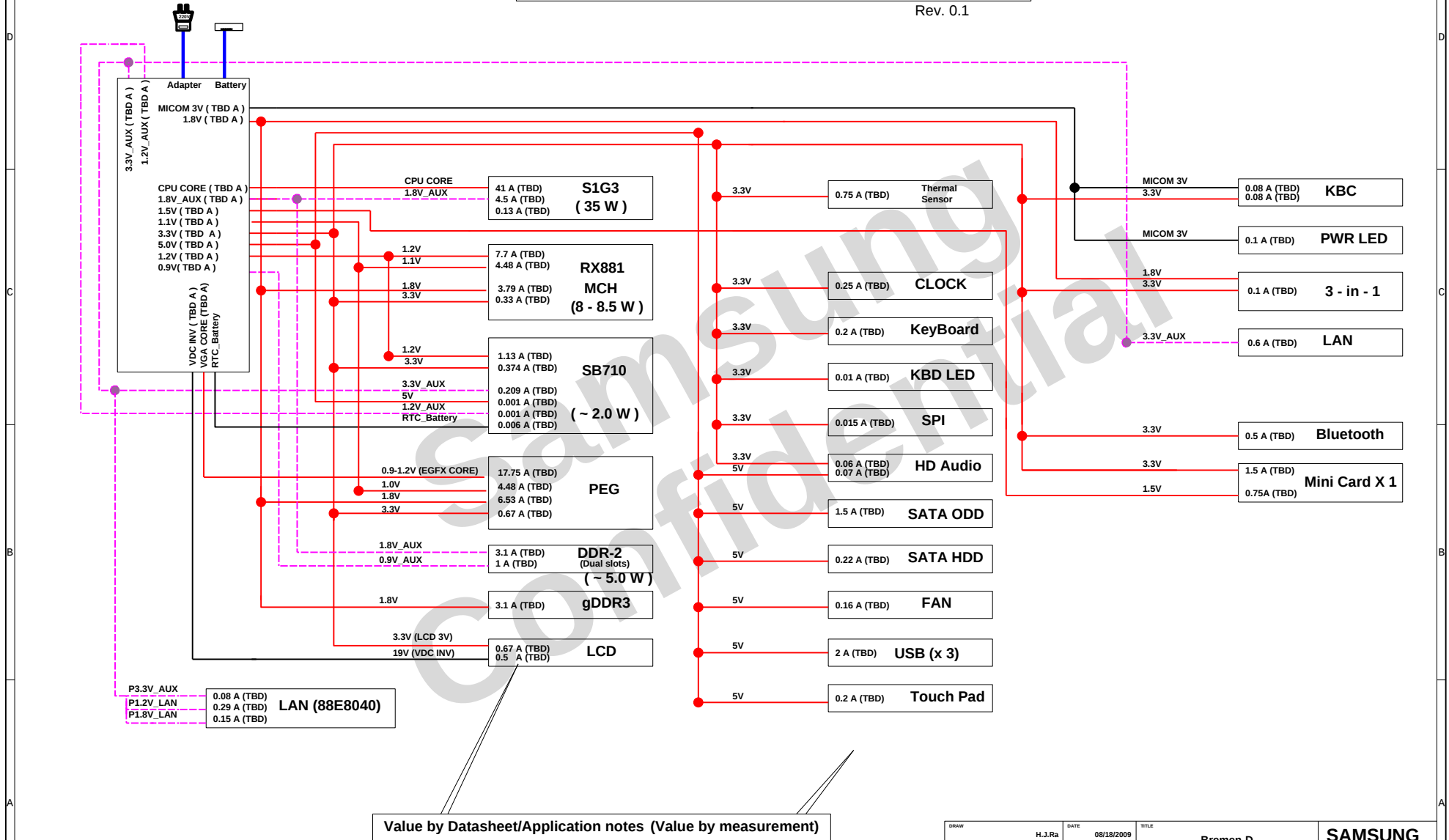
S0

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POWER RAILS ANALYSIS

Rev. 0.1



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Host Boot / ME Off
(SLPS4* = S4_STATE*) > (SLPM* = SLPS3*)
M-1) KBC3_DDR_PWRON (TBD) = 8) KBC3_SUSPWR
M-2) KBC3_ME_PWRON = 15) KBC3_PWRON

Host / ME Boot
(SLPS4* = S4_STATE*) > SLPM* > SLPS3*

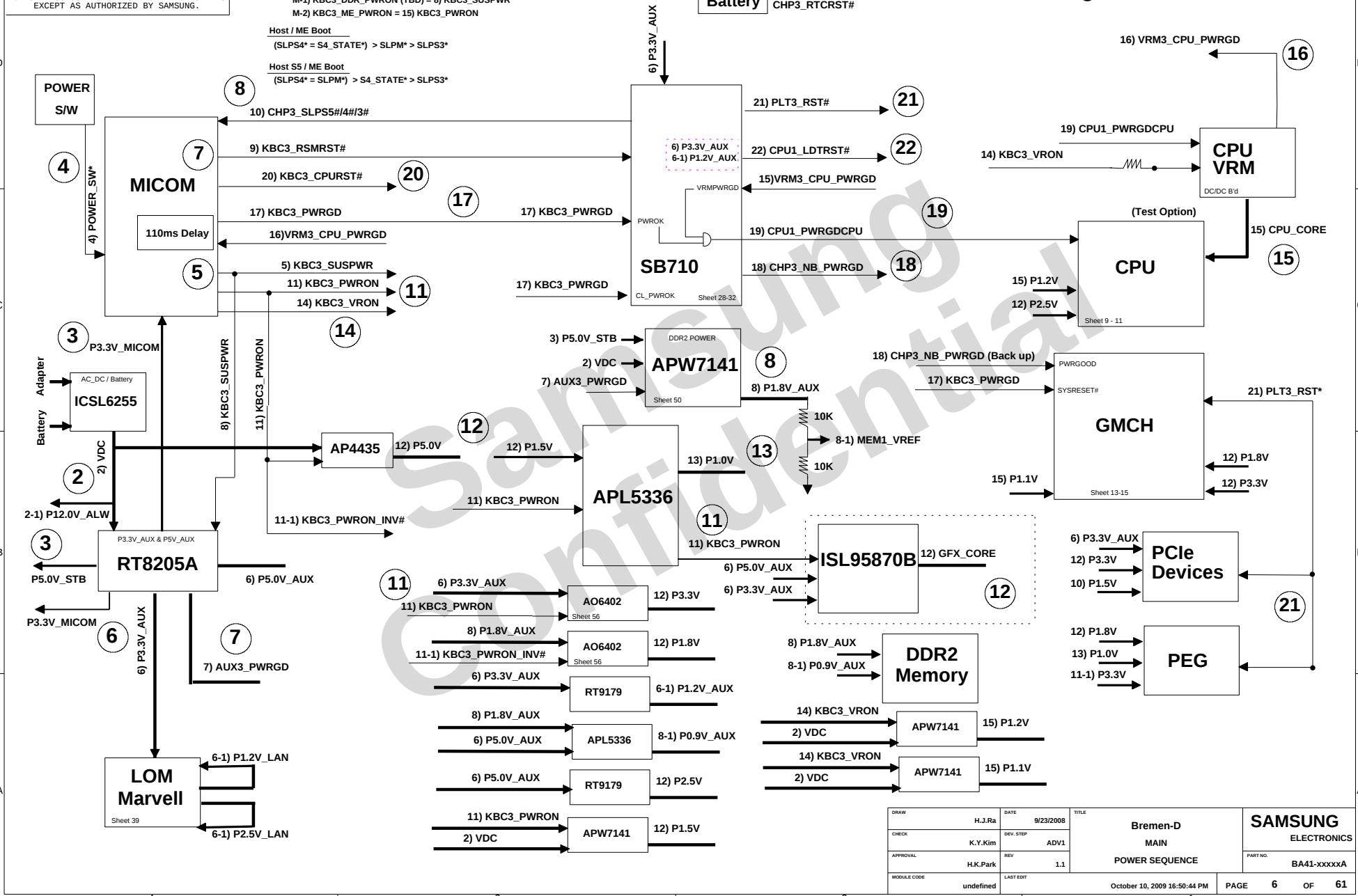
Host S5 / ME Boot
(SLPS4* = SLPM*) > S4_STATE* > SLPS3*

RTC Battery

PRTC_BAT
CHP3_RTCSRST#

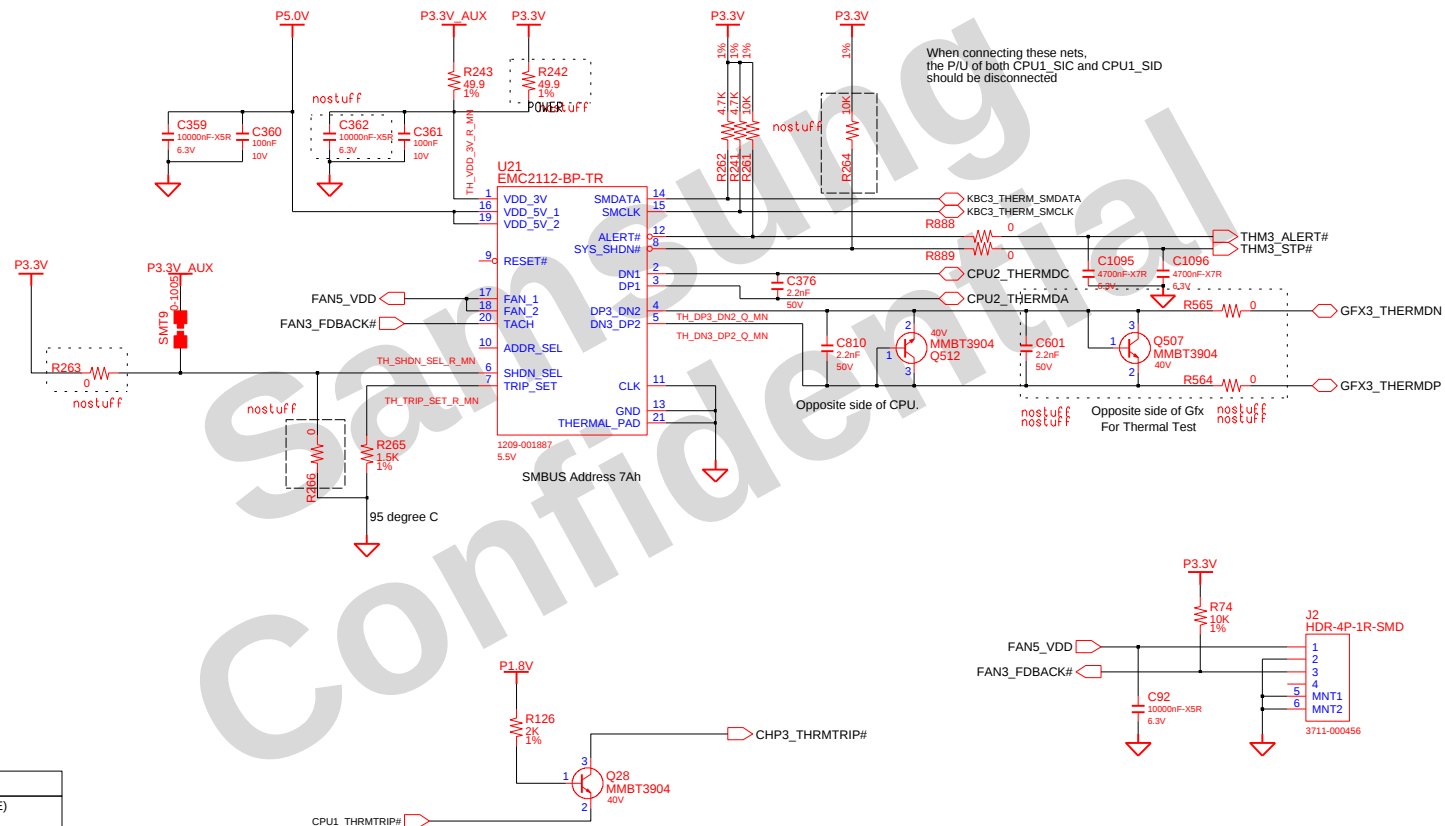
POWER SEQUENCE

Rev. 0.3





THERMAL SENSOR & FAN CONTROL

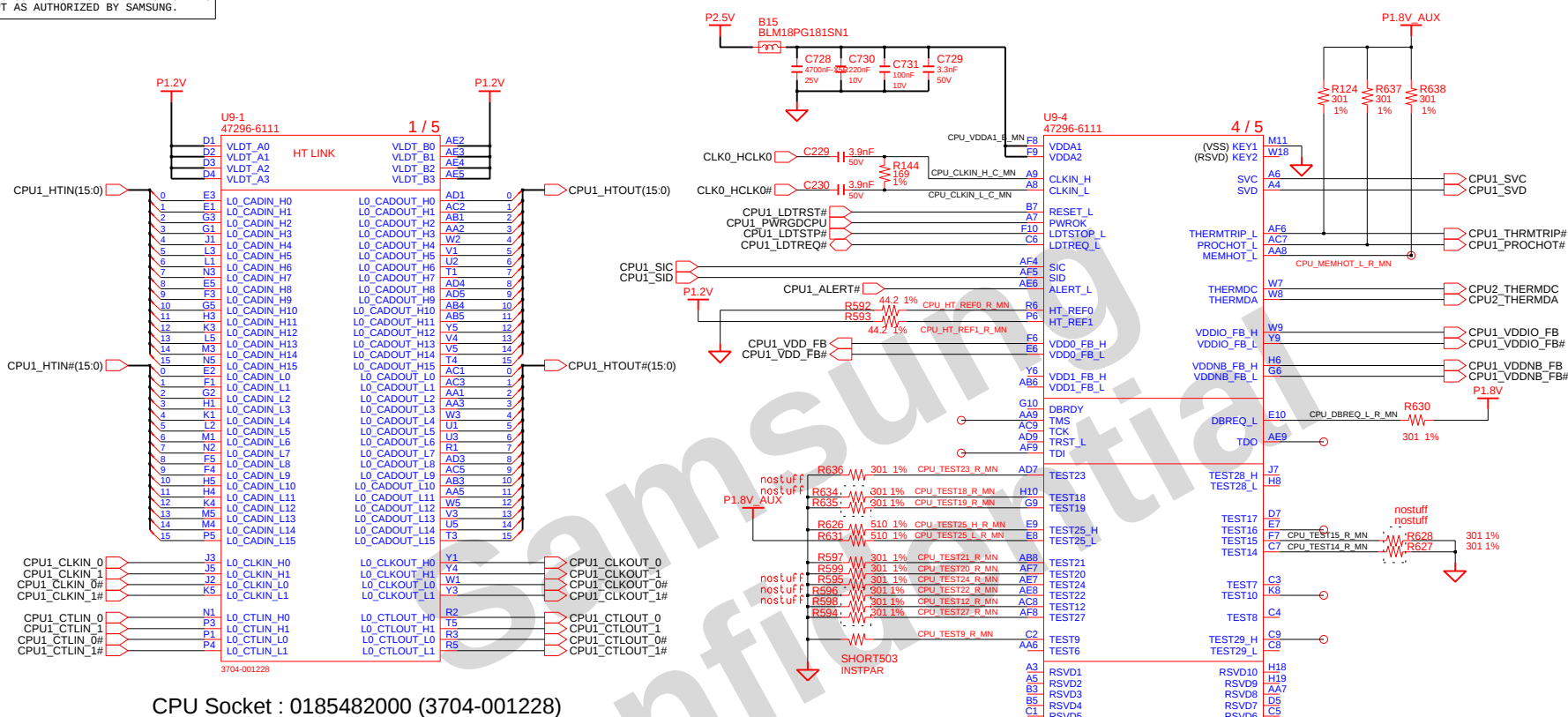


SHDN_SEL MODE	
0	CH1(CPU MODE)
HIGH Z	CH3(DIODE MODE)
1	N/A (SHDN# NOT USED)

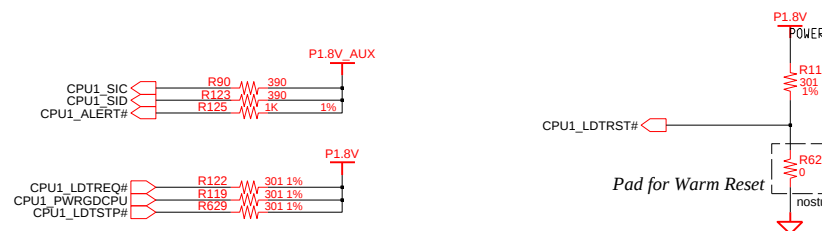
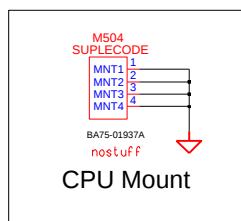
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CHECK	K.Y.Kim	DEV. STEP	ADV1		THERMAL SENSOR
APPROVAL	H.K.Park	REV	1.1		THERMAL SENSOR EMC2112
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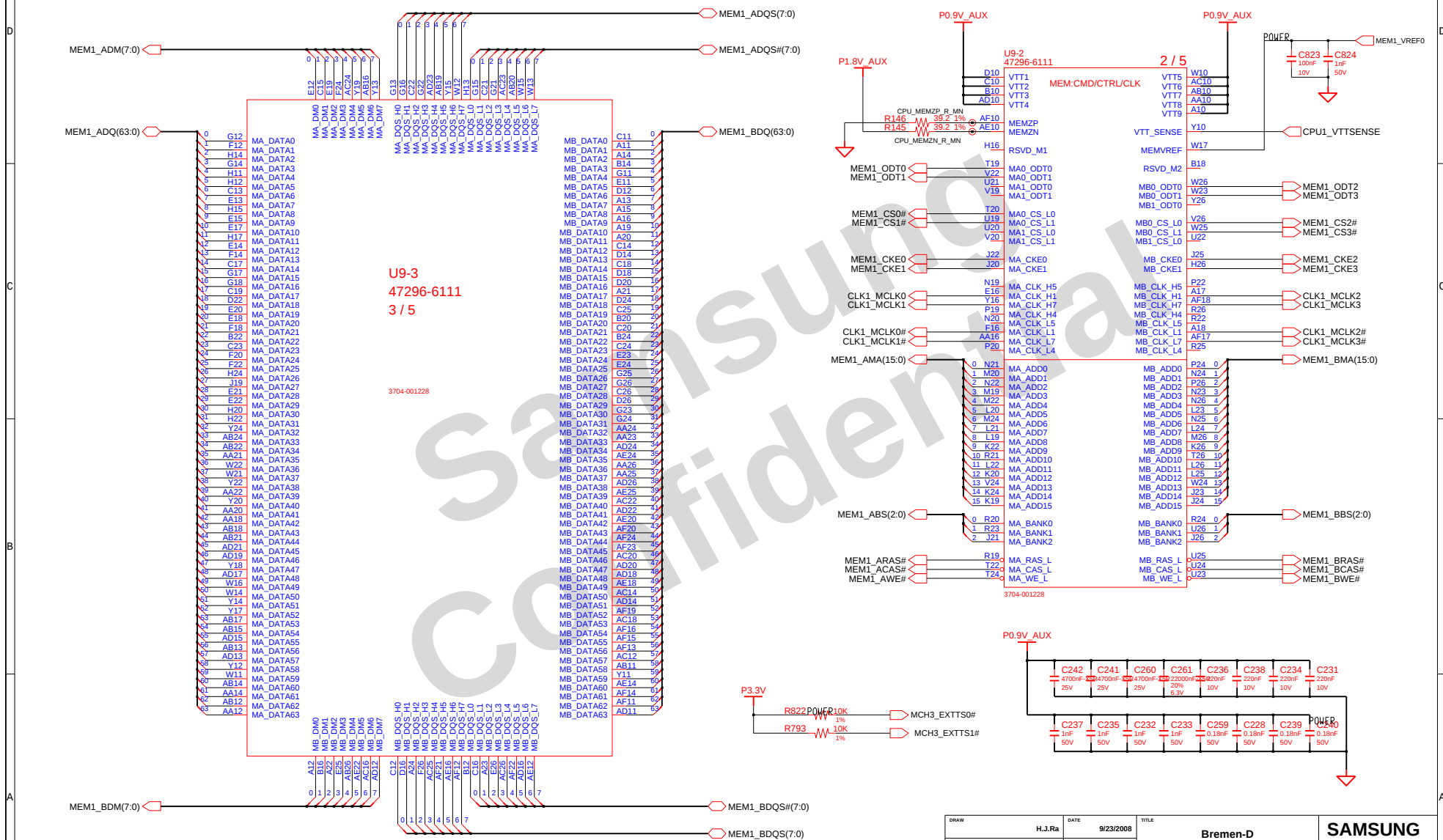


CPU Socket : 0185482000 (3704-001228)



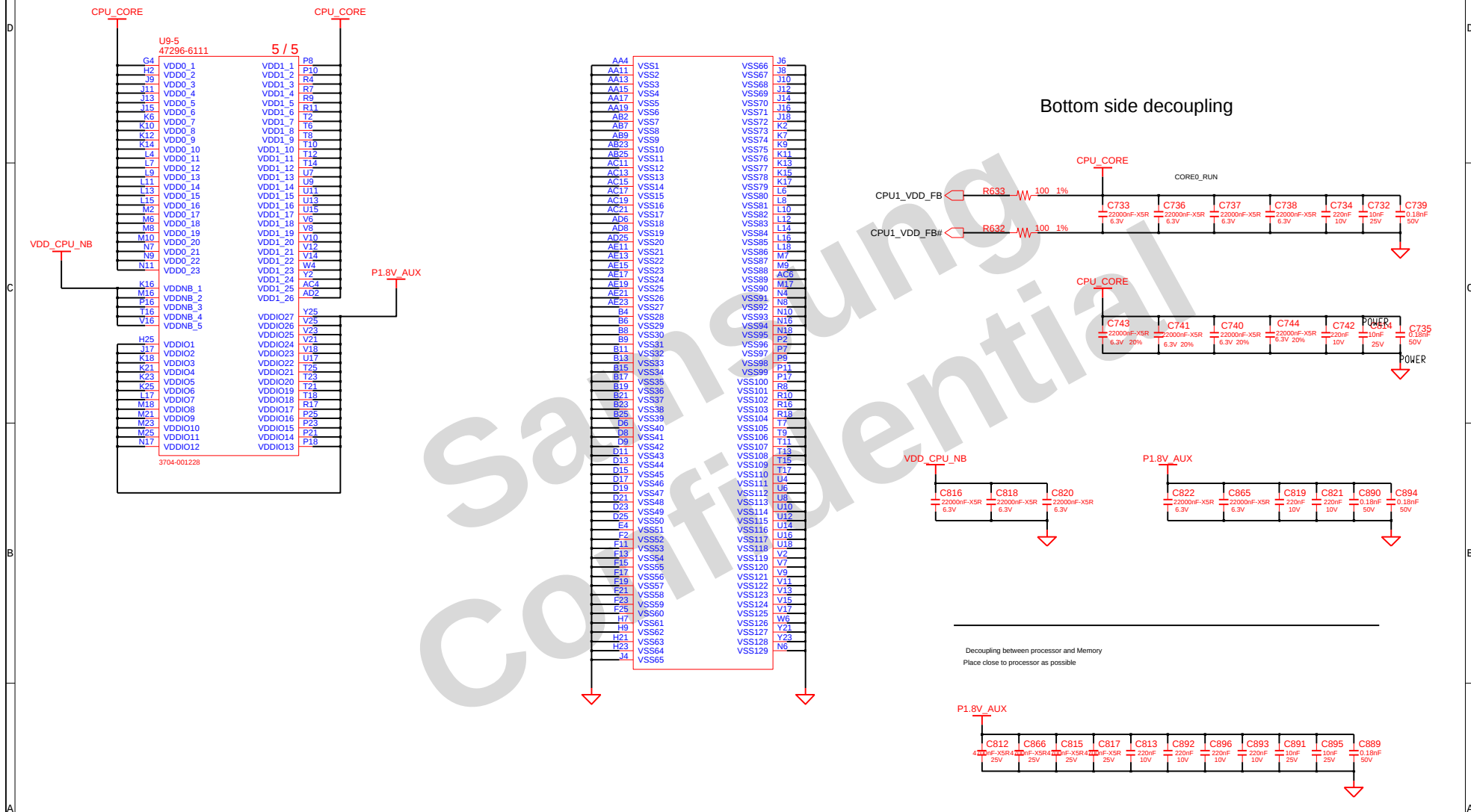
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CPU_Caspian



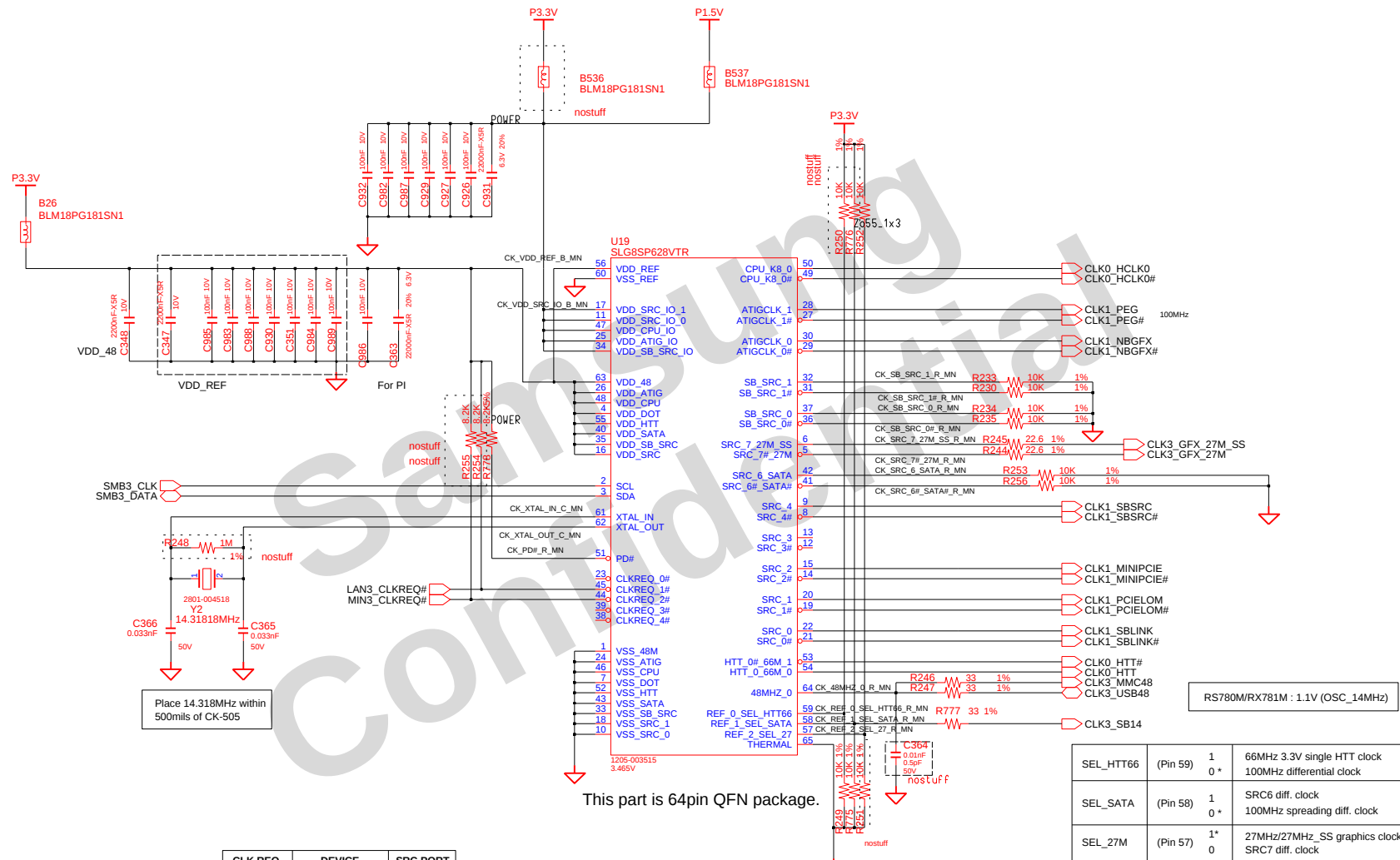
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APPROVAL	H.K.Park	REV	1.1		PART NO.	BA41-xxxxxA
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CPU_Caspian



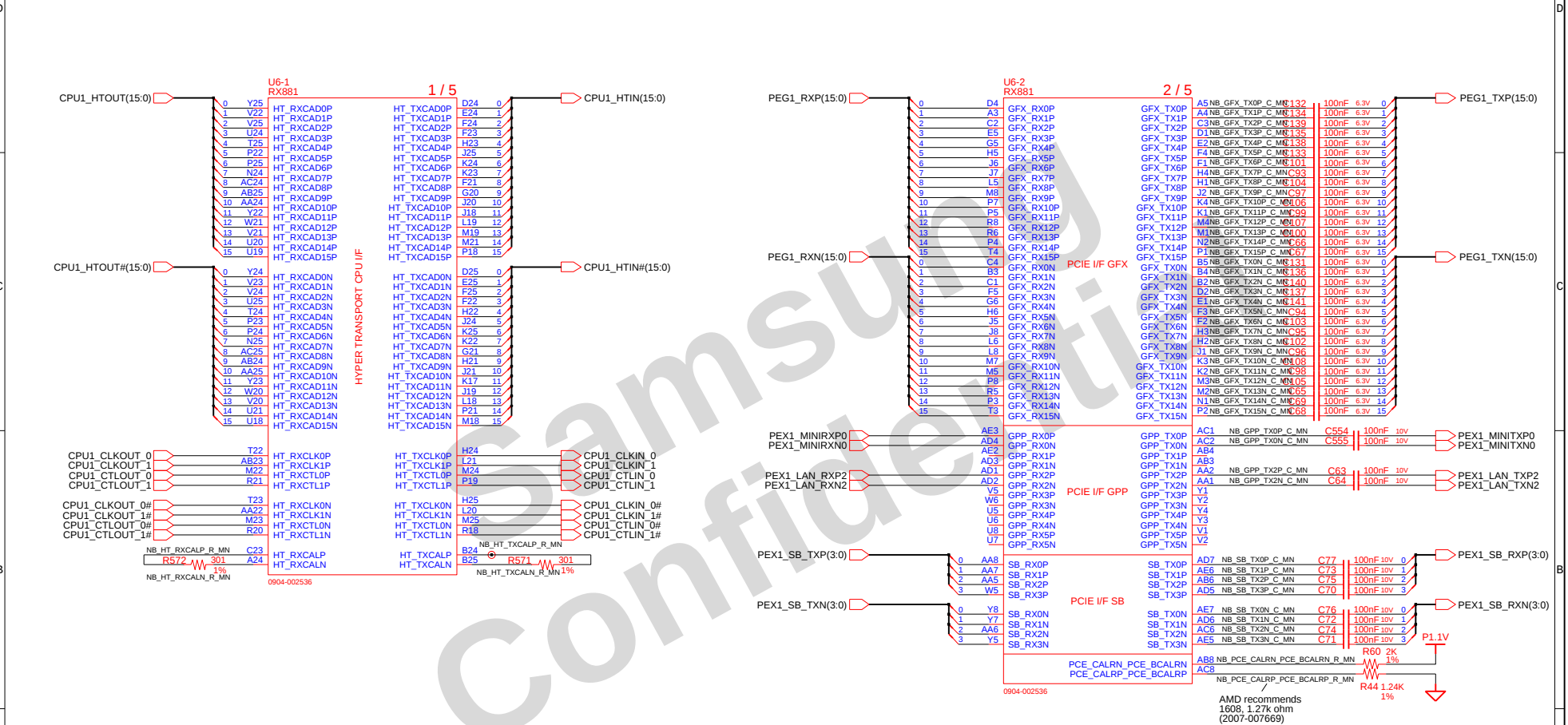
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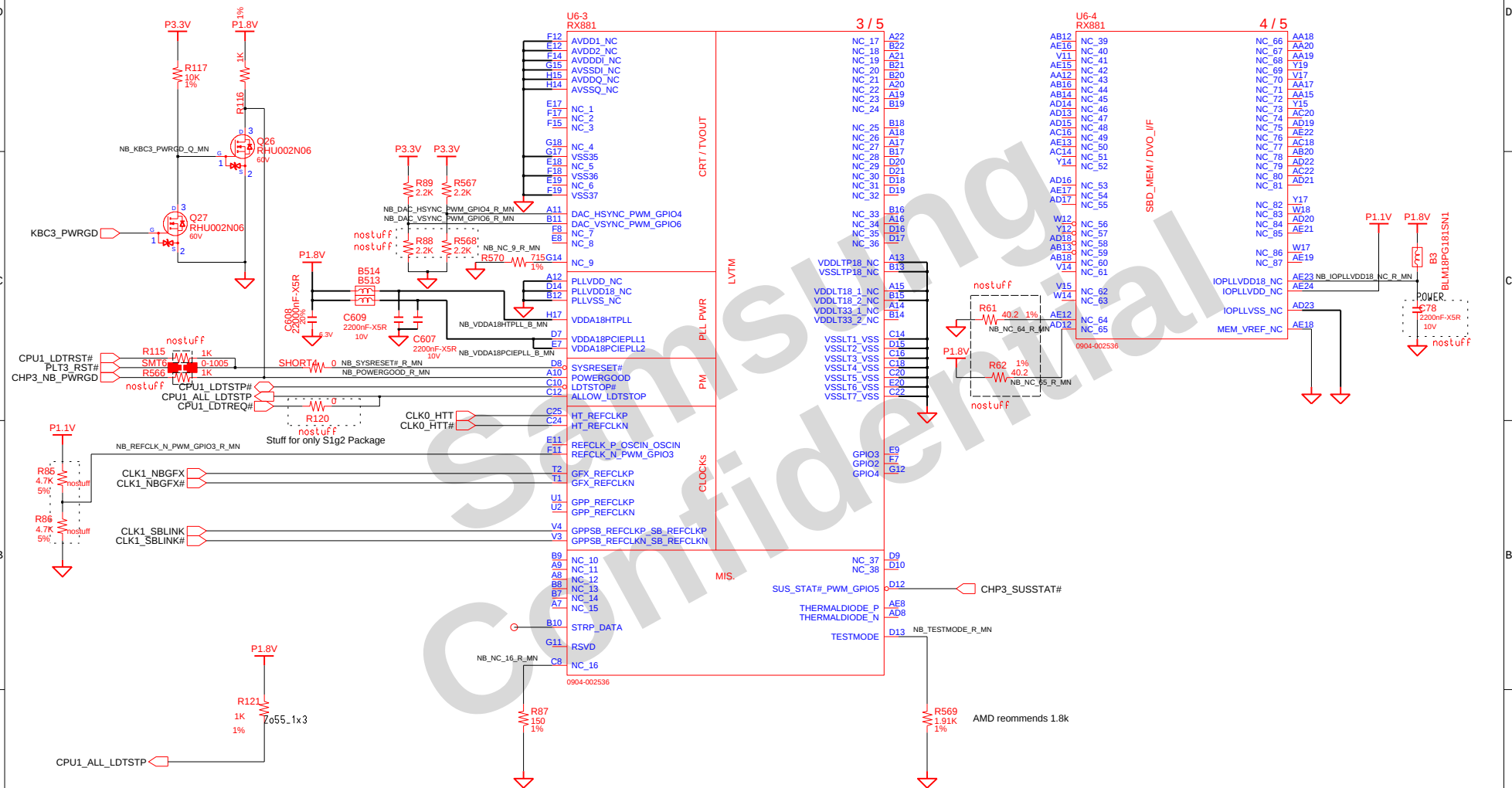
NB_RX881_AMD

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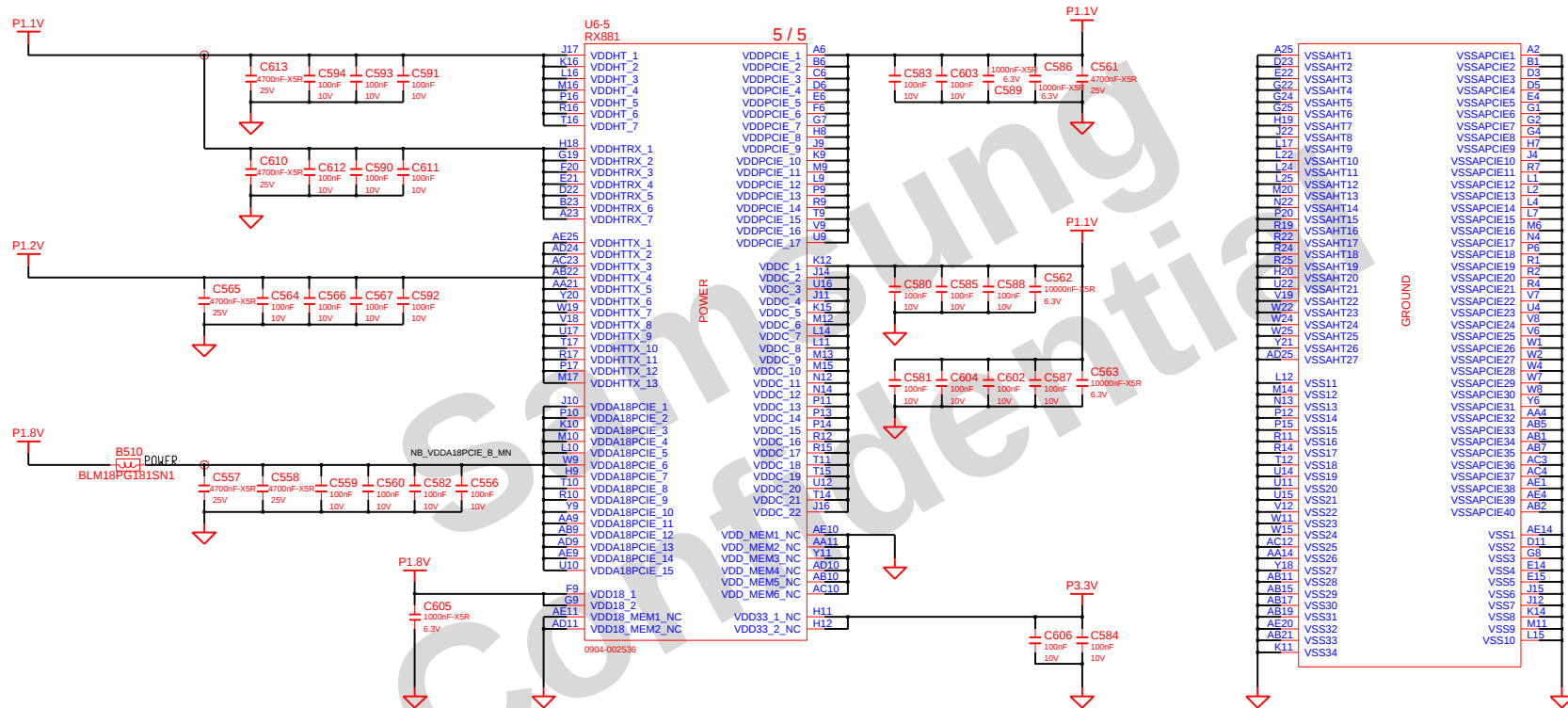
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CHECK	K.Y.Kim	DEV. STEP	ADV1		MCH_DDR2	
APPROVAL	H.K.Park	REV	1.1		RX881 (1/3)	
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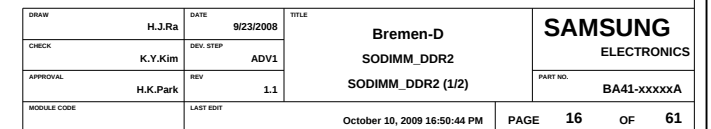


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APPROVAL	H.K.Park	REV	1.1		RX881 (2/3)	PART NO.
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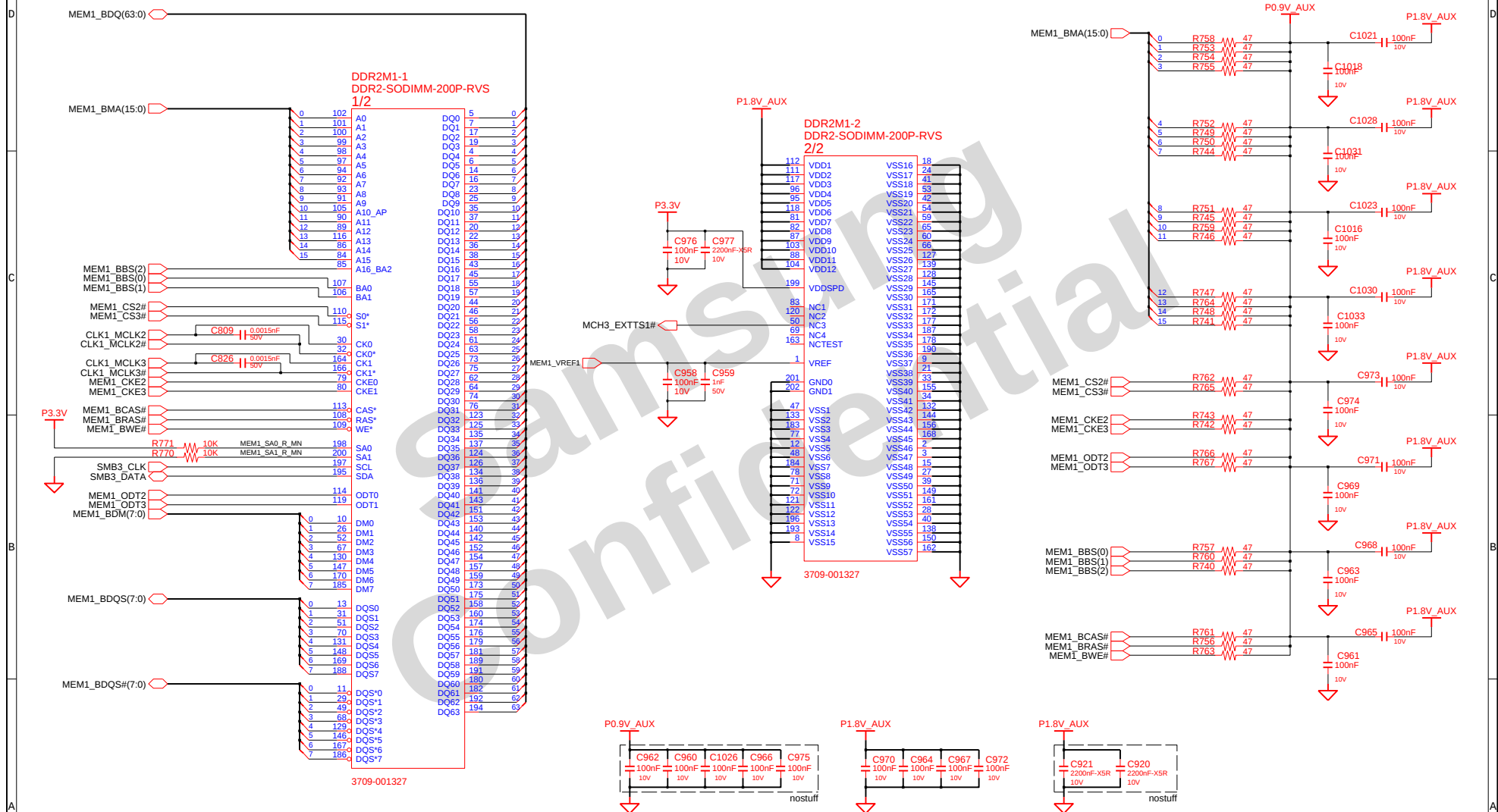


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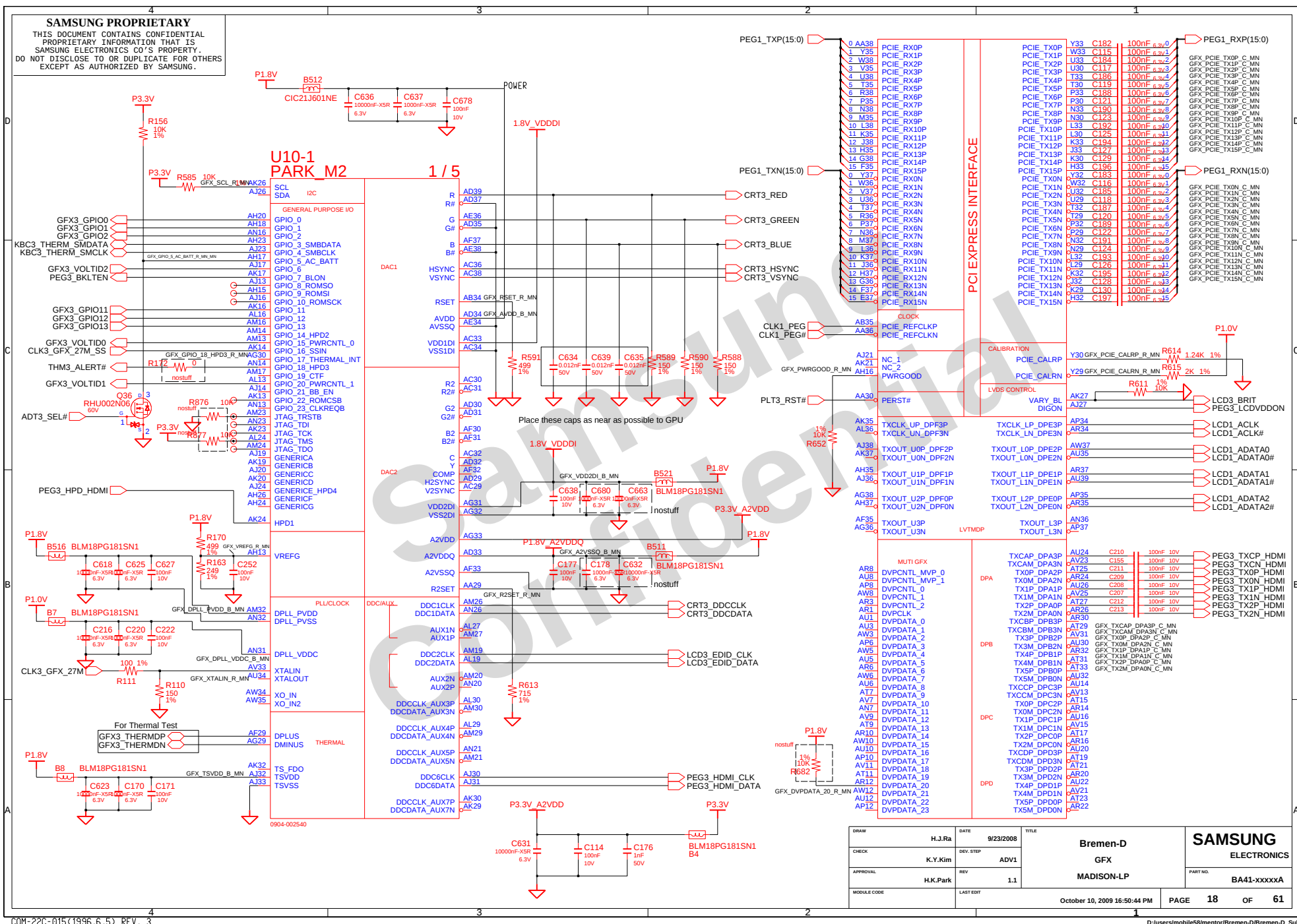


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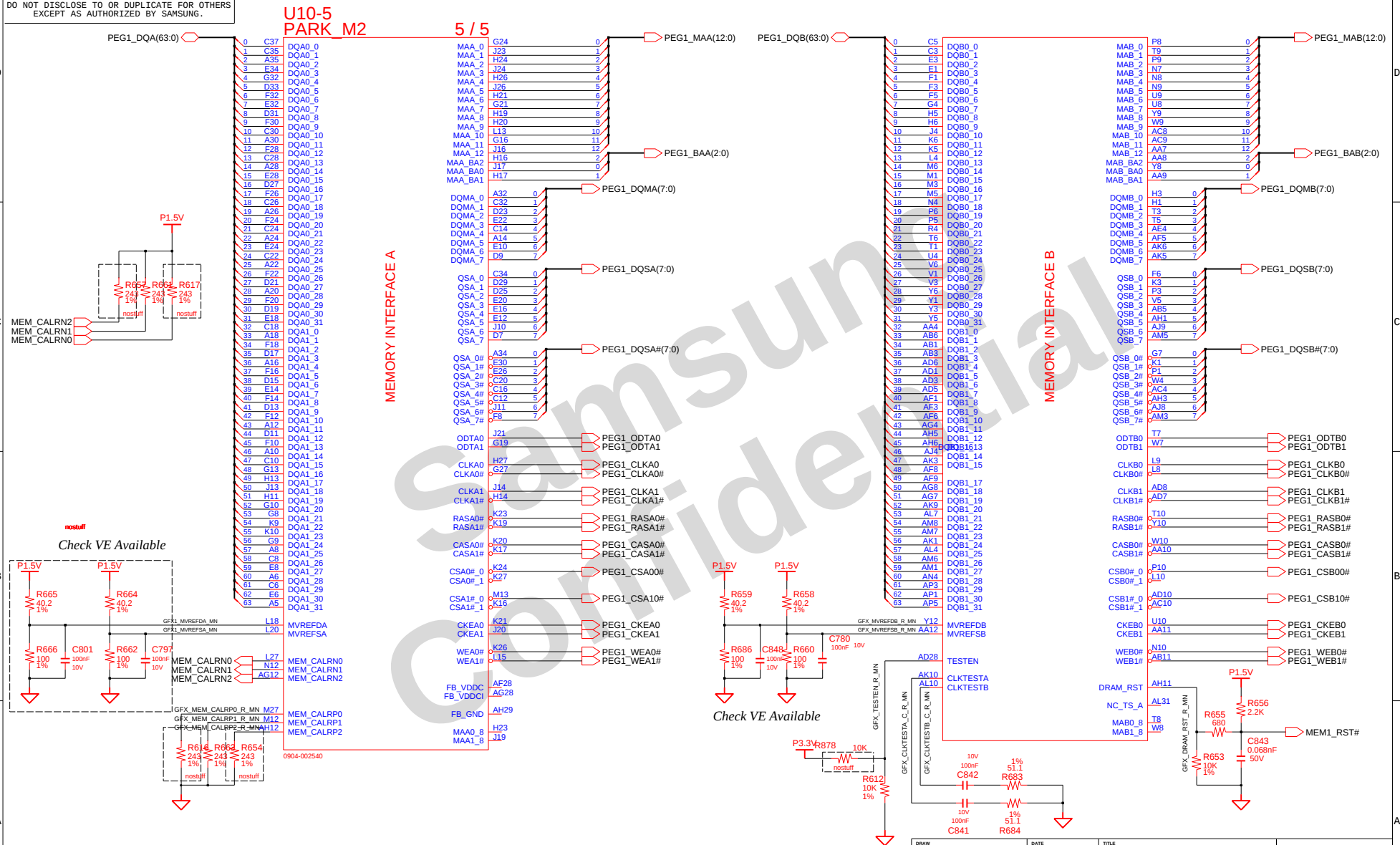
DDR SO-DIMM #1



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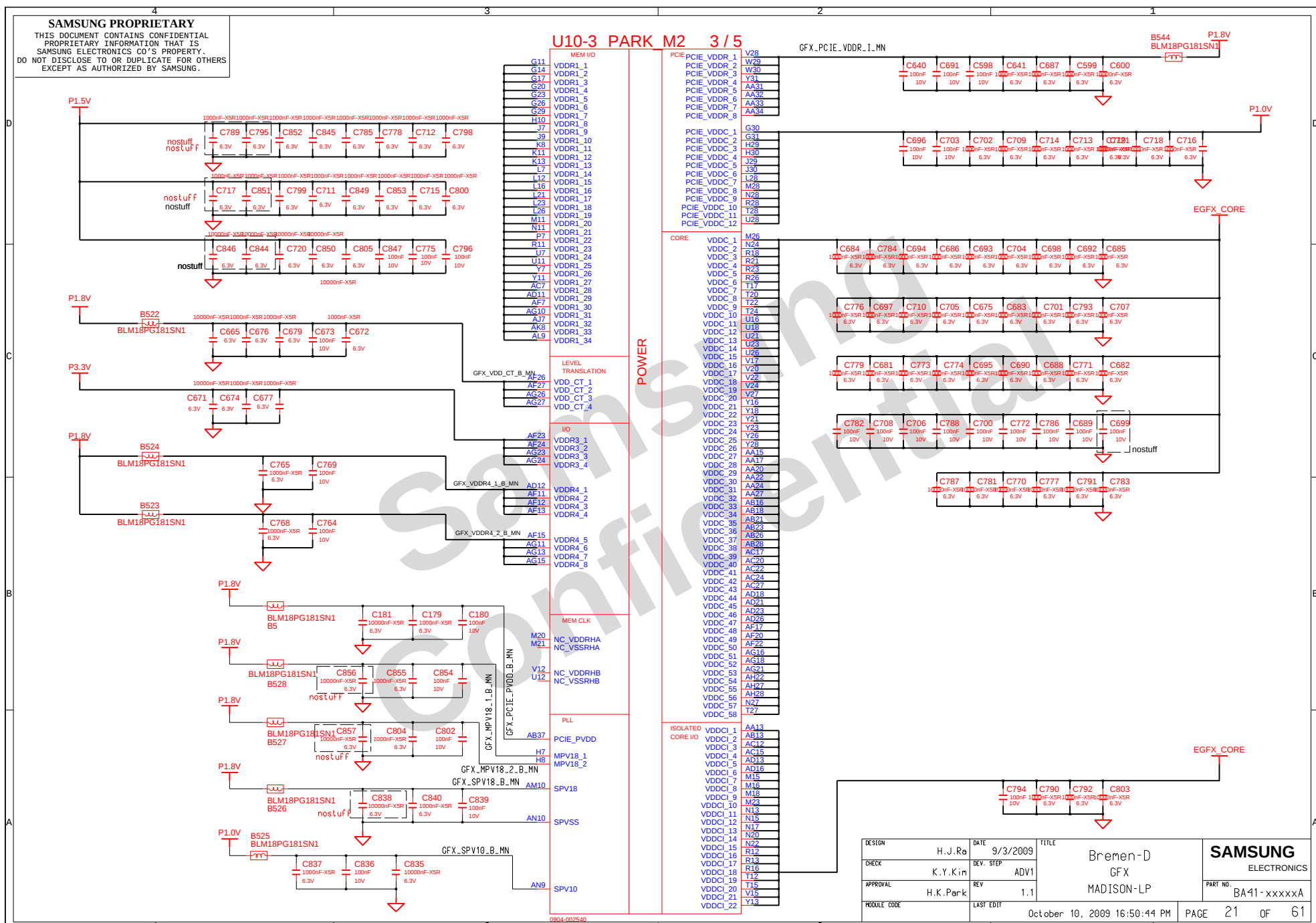


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APPROVAL	H.K.Rev	REV	1.1								
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U10-2
PARK M2 2 / 5

E39 PCIE_VSS_1
F34 PCIE_VSS_2
F39 PCIE_VSS_3
G33 PCIE_VSS_4
G34 PCIE_VSS_5
H31 PCIE_VSS_6
H34 PCIE_VSS_7
H39 PCIE_VSS_8
J31 PCIE_VSS_9
J34 PCIE_VSS_10
K31 PCIE_VSS_11
K34 PCIE_VSS_12
K39 PCIE_VSS_13
L31 PCIE_VSS_14
L34 PCIE_VSS_15
M34 PCIE_VSS_16
M39 PCIE_VSS_17
N31 PCIE_VSS_18
N34 PCIE_VSS_19
P31 PCIE_VSS_20
P34 PCIE_VSS_21
P39 PCIE_VSS_22
R34 PCIE_VSS_23
T31 PCIE_VSS_24
T34 PCIE_VSS_25
T39 PCIE_VSS_26
U31 PCIE_VSS_27
U34 PCIE_VSS_28
V34 PCIE_VSS_29
V39 PCIE_VSS_30
W31 PCIE_VSS_31
W34 PCIE_VSS_32
Y34 PCIE_VSS_33
Y39 PCIE_VSS_34
AB39 PCIE_VSS_35

GND

AA16 GND_101
AA19 GND_102
AA21 GND_103
AA23 GND_104
AA26 GND_105
AA28 GND_106
AB12 GND_107
AB15 GND_108
AB17 GND_109
AB20 GND_110
AB22 GND_111
AB27 GND_112
AC11 GND_113
AC13 GND_114
AC16 GND_115
AC18 GND_116
AC2 GND_117
AC6 GND_118
GND_119

0904-002540

A3 GND_1
A37 GND_2
B7 GND_3
B9 GND_4
B11 GND_5
B13 GND_6
B15 GND_7
B17 GND_8
B19 GND_9
B21 GND_10
B23 GND_11
B25 GND_12
B27 GND_13
B29 GND_14
B31 GND_15
B33 GND_16
C1 GND_17
C39 GND_18
E5 GND_19
E35 GND_20
F7 GND_21
F9 GND_22
F11 GND_23
F13 GND_24
F15 GND_25
F17 GND_26
F19 GND_27
F21 GND_28
F23 GND_29
F25 GND_30
F27 GND_31
F29 GND_32
F31 GND_33
F33 GND_34
G2 GND_35
G6 GND_36
H9 GND_37
J2 GND_38
J6 GND_39
J8 GND_40
J27 GND_41
K7 GND_42
K14 GND_43
L2 GND_44
L6 GND_45
L11 GND_46
L17 GND_47
L24 GND_48
L29 GND_49
M17 GND_50
M22 GND_51
M24 GND_52
N2 GND_53
N6 GND_54
N16 GND_55
N18 GND_56
N23 GND_57
N25 GND_58
R2 GND_59
GND_60

AC21 GND_120
AC23 GND_121
AC26 GND_122
AC28 GND_123
AD9 GND_124
AD13 GND_125
AD17 GND_126
AD20 GND_127
AD22 GND_128
AD24 GND_129
AE2 GND_130
AE6 GND_131
AF10 GND_132
AF18 GND_133
AF19 GND_134
AF21 GND_135
AG2 GND_136
AG6 GND_137
AG9 GND_138
AG17 GND_139
AG20 GND_140
AG22 GND_141
AG23 GND_142
AG24 GND_143
AJ2 GND_144
AJ6 GND_145
AJ10 GND_146
AJ11 GND_147
AJ28 GND_148
AK7 GND_149
AK11 GND_150
AK31 GND_151
AL2 GND_152
AL5 GND_153
AL8 GND_154
AL11 GND_155
AL14 GND_156
J2 GND_157
AL20 GND_158
AR5 GND_159
AL23 GND_160
AL26 GND_161
AL32 GND_162
AM9 GND_163
AM11 GND_164
AM31 GND_165
AM15 GND_166
AN2 GND_167
AN6 GND_168
AN8 GND_169
AN30 GND_170
AP7 GND_171
AP9 GND_172
AP11 GND_173
AL21 GND_174

GND

R6 GND_61
R15 GND_62
R17 GND_63
R20 GND_64
R22 GND_65
R24 GND_66
R27 GND_67
T11 GND_68
T13 GND_69
T16 GND_70
T18 GND_71
T21 GND_72
T23 GND_73
T26 GND_74
U2 GND_75
U6 GND_76
U13 GND_77
U15 GND_78
U17 GND_79
U20 GND_80
U22 GND_81
U24 GND_82
U27 GND_83
V11 GND_84
V13 GND_85
V15 GND_86
V18 GND_87
V21 GND_88
V23 GND_89
V26 GND_90
W2 GND_91
W6 GND_92
Y15 GND_93
Y17 GND_94
Y20 GND_95
Y22 GND_96
Y24 GND_97
Y27 GND_98
AA2 GND_99
AA6 GND_100

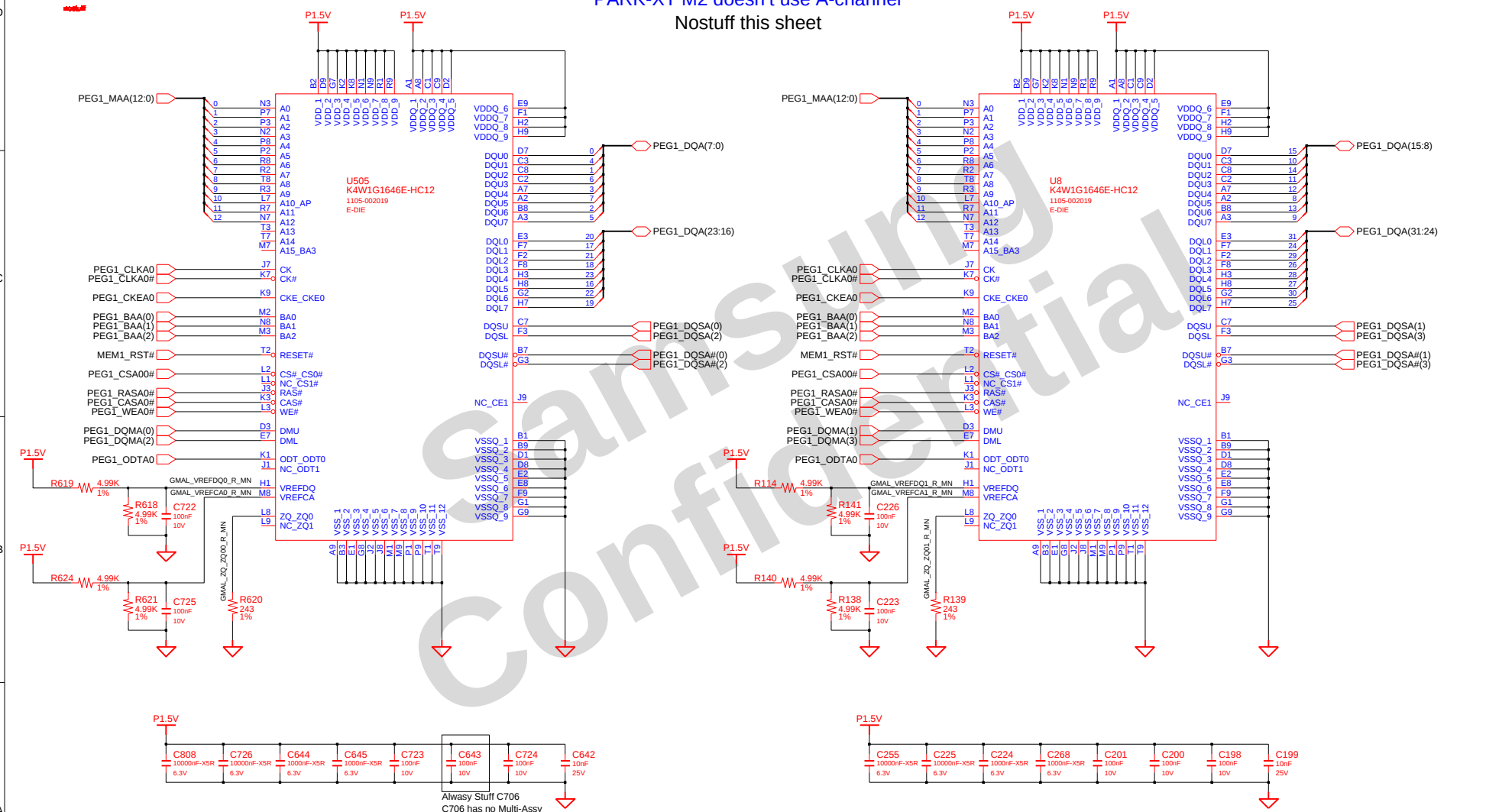
VSS_MECH_1 A39
VSS_MECH_2 AW1
VSS_MECH_3 AW39

DESIGN	H.J.Ro	DATE	9/3/2009	TITLE	Bremen-D GFX MADISON-LP	SAMSUNG ELECTRONICS
CHECK	K.Y.Kim	DEV. STEP	ADV1			PART NO. BA41-xxxxxA
APPROVAL	H.K.Park	REV	1.1			
MODULE CODE		LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	22	OF 61

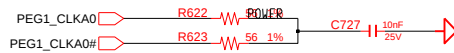
A-channel Lower Data

PARK-XT M2 doesn't use A-channel

Nostuff this sheet



Always Stuff C706
C706 has no Multi-Assy

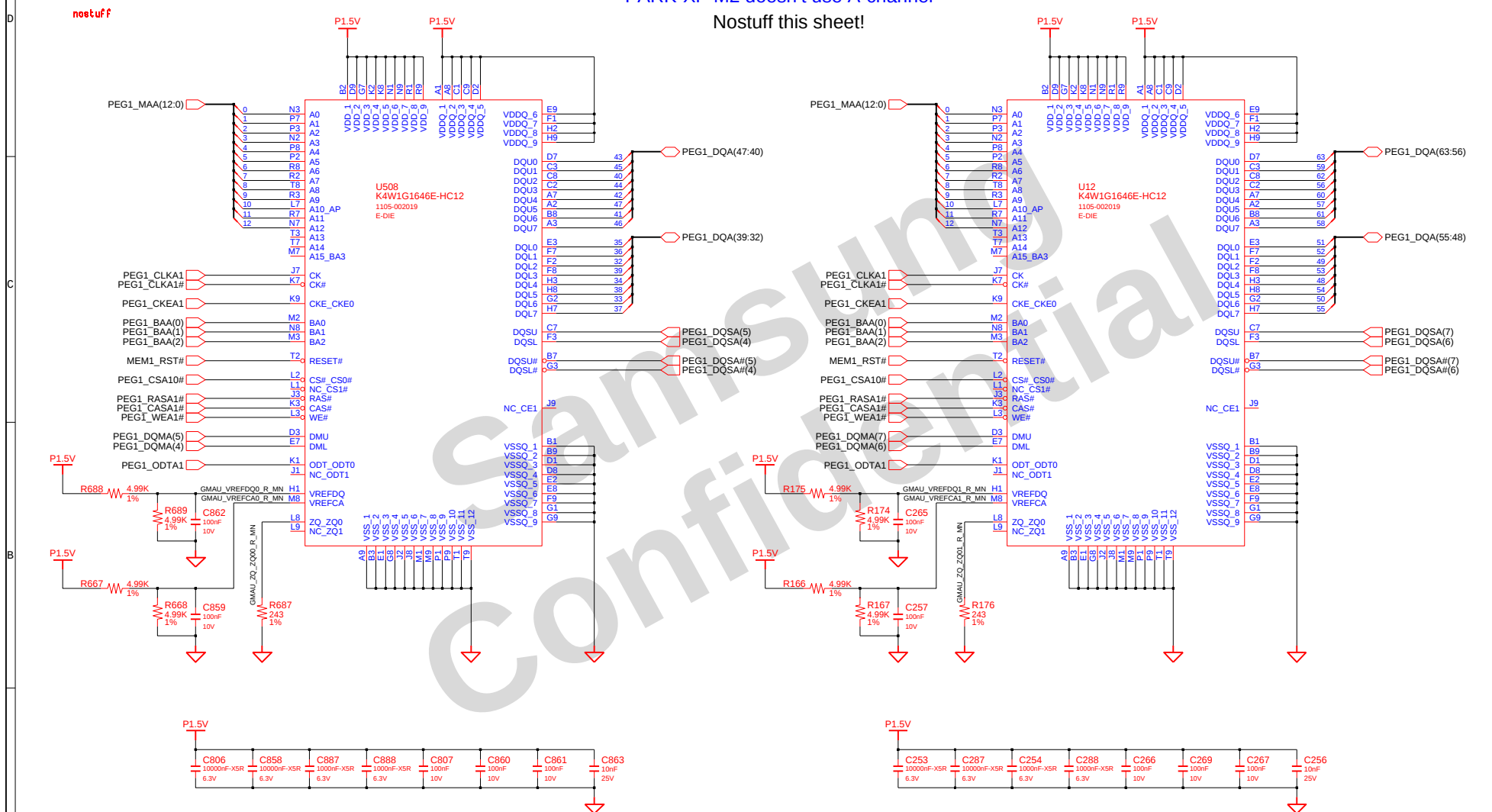


DESIGN	H.J.Ro	DATE	9/3/2009	TITLE	Bremen-D GRAPHICS MEMORY gDDR3	SAMSUNG ELECTRONICS PART NO. BA41-xxxxxA
CHECK	K.Y.Kim	DEV. STEP	ADV1			
APPROVAL	H.K.Park	REV	1.1			
MODULE CODE		LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	23 OF 61	

A-channel Upper Data

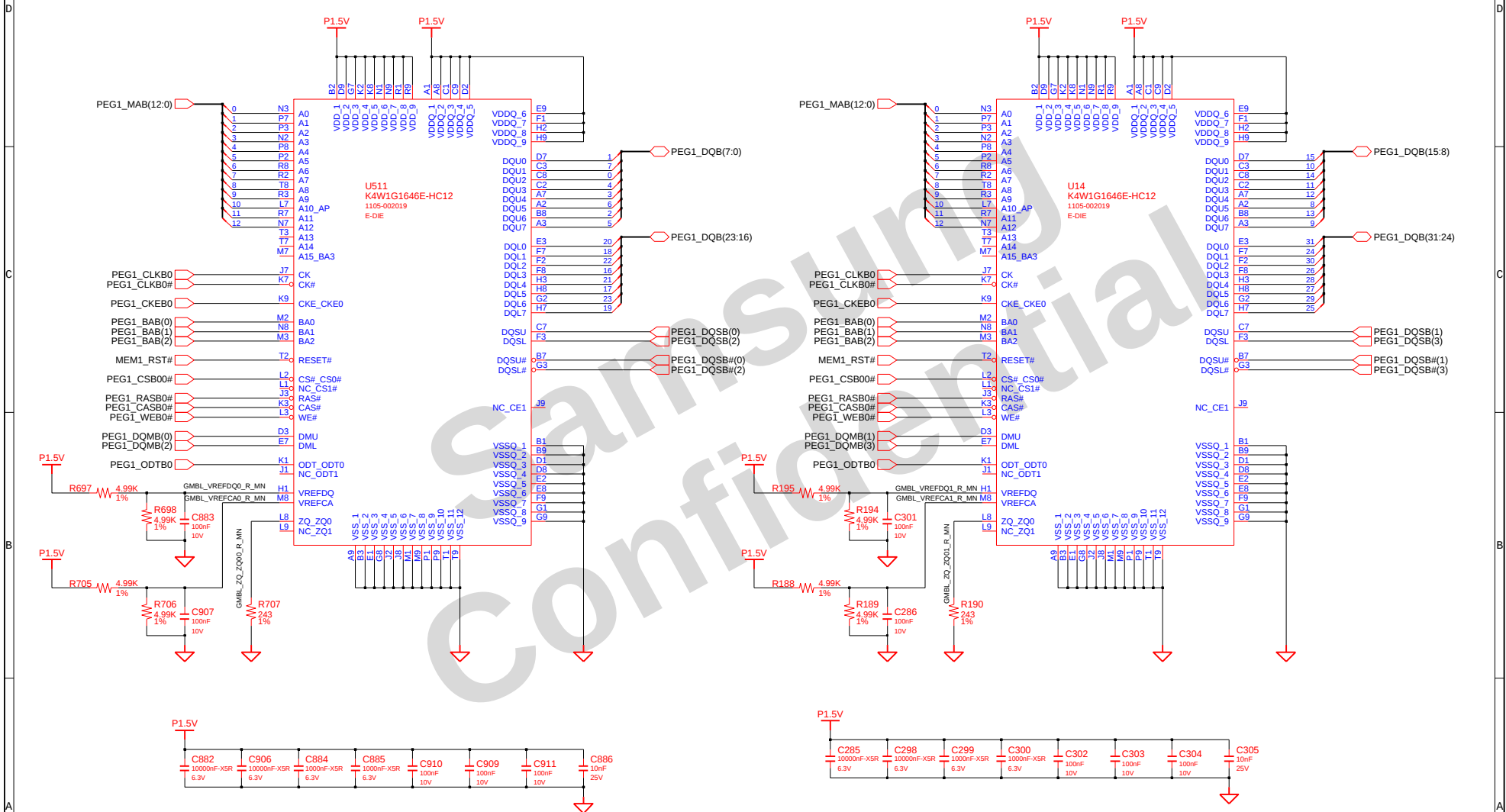
PARK-XP M2 doesn't use A-channel

Nostuff this sheet!



DESIGN	H. J. Ra	DATE	9/3/2009	TITLE Bremen-D GRAPHICS MEMORY gDDR3	SAMSUNG ELECTRONICS
CHECK	K. Y. Kim	DEV. STEP	ADV1		
APPROVAL	H. K. Park	REV	1.1		
MODULE CODE	LAST EDIT		October 10, 2009 16:50:44 PM		

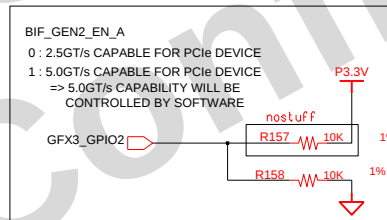
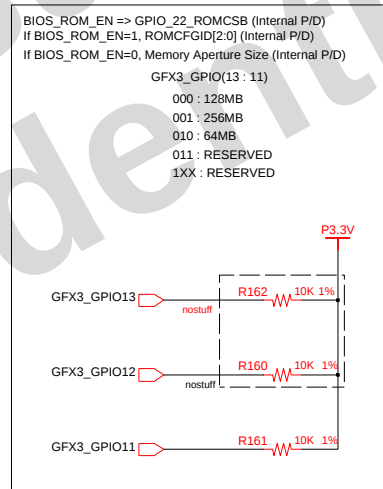
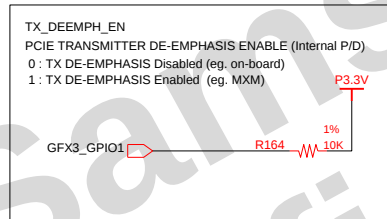
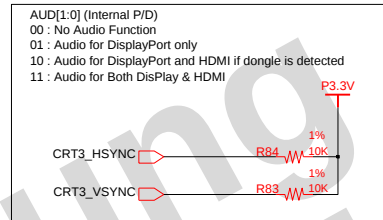
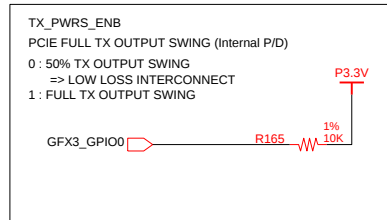
B-channel Lower Data



PEG1_CLKB0 56 1%
PEG1_CLKB0# 56 1%
C908 25V

DESIGN	H.J.Ro	DATE	9/3/2009	TITLE	Bremen-D GRAPHICS MEMORY gDDR3	SAMSUNG ELECTRONICS PART NO. BA41-xxxxxA
CHECK	K.Y.Kim	DEV. STEP	ADV1			
APPROVAL	H.K.Park	REV	1.1			
MODULE CODE		LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	25 OF 61	

Park XT Straps



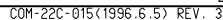
DESIGN	H.J.Ro	DATE	9/3/2009	TITLE	Bremen-D GFX MADISON-LP	SAMSUNG ELECTRONICS
CHECK	K.Y.Kim	DEV. STEP	ADV1			PART NO. BA41-xxxxxA
APPROVAL	H.K.Park	REV	1.1			
MODULE CODE		LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	27	OF 61

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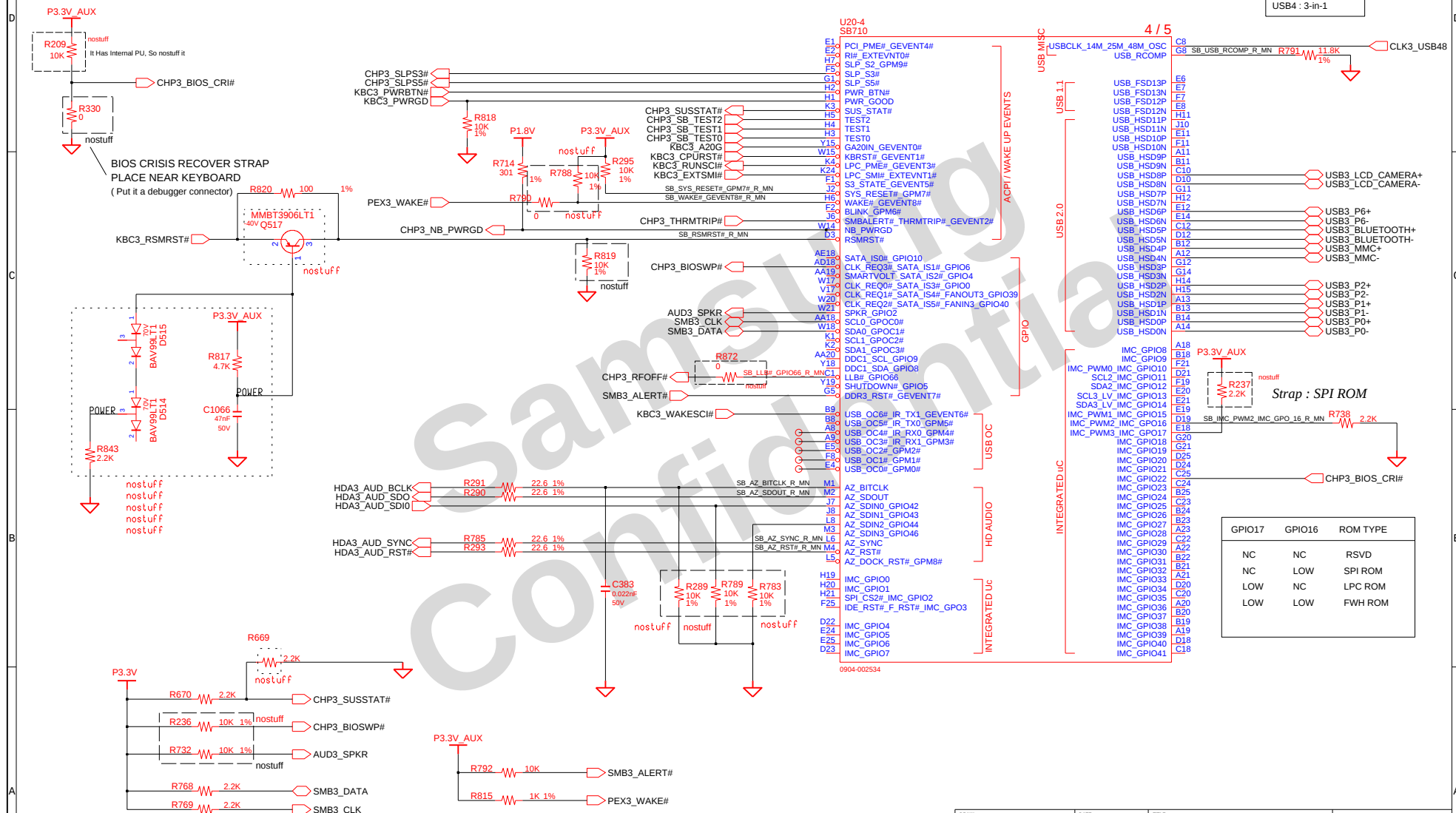
DESIGN	H. J. Rø	DATE	9/3/2009	TITLE Bremen-D ICH SB710 (1/5)	
CHECK	K. Y. Kim	DEV. STEP	ADV1		
APPROVAL	H. K. Park	REV	1.1		
MODULE CODE	LAST EDIT		October 10, 2009 16:50:44 PM		
			PAGE	28	OF 61

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D:/users/mobile58/mentor/Bremen-D/Bremen-D_Sub

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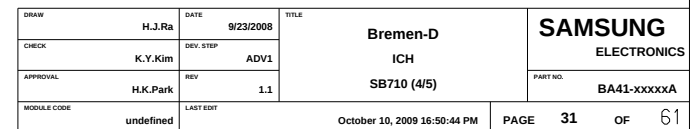
USB1, 6 : Right Port
USB0 : Left Port
USB5 : Bluetooth
USB8 : Camera
USB4 : 3-in-1



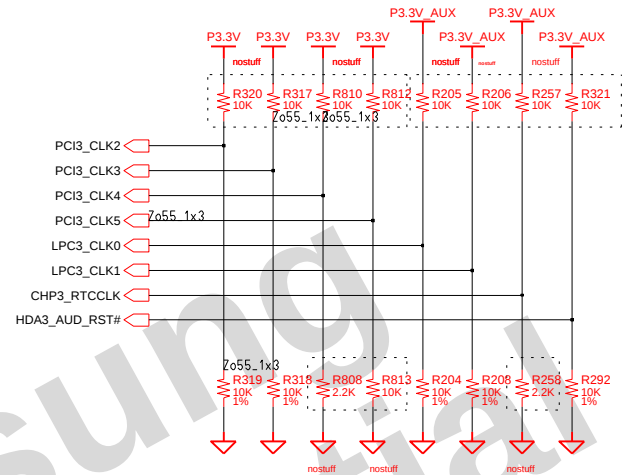
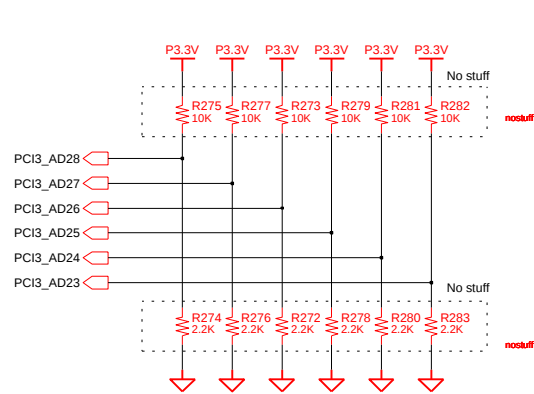
GPIO17	GPIO16	ROM TYPE
NC	NC	RSVD
NC	LOW	SPI ROM
LOW	NC	LPC ROM
LOW	LOW	FWH ROM

DRAW	H.J.Ra	DATE	9/23/2008	Bremen-D ICH SB710 (3/5)	SAMSUNG ELECTRONICS	
CHECK	K.Y.Kim	DEV. STEP	ADV1			
APPROVAL	H.K.Park	REV	1.1		PART NO.	BA41-XXXXA
MODULE CODE	LAST EDIT				October 10, 2009 16:50:44 PM	PAGE 30 OF 61

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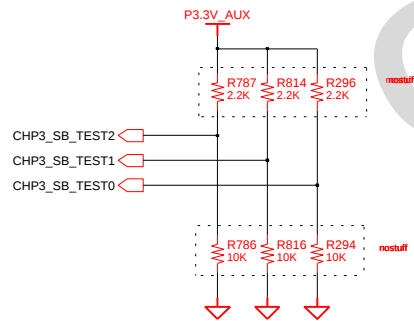
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DEBUG STRAPS

	PCI3_AD(28)	PCI3_AD(27)	PCI3_AD(26)	PCI3_AD(25)	PCI3_AD(24)	PCI3_AD(23)
STRAP HIGH	USE LONG RESET	USE PCI PLL	USE ACPI BCLK	USE IDE PLL	USE DEFAULT PCIE STRAPS	BOOTFAILTIMER DISABLED
STRAP LOW	USE SHORT RESET	BYPASS PCI PLL	BYPASS ACPI BCLK	BYPASS IDE PLL	USE EEPROM PCIE STRAPS	BOOTFAILTIMER ENABLED

	PCI3_CLK2	PCI3_CLK3	PCI3_CLK4	PCI3_CLK5	LPC3_CLK0	LPC3_CLK1	RTC_CLK	AUD_RST#
STRAP HIGH	BOOTFAIL TIMER ENABLED	USER DEBUG STRAPS	RESERVED	RESERVED	EC ENABLED	CLKGEN ENABLED	INTERNAL RTC	ENABLE PCI MEM BOOT
STRAP LOW	BOOTFAIL TIMER DISABLED	IGNORE DEBUG STRAPS	RESERVED	RESERVED	EC DISABLED	CLKGEN DISABLED	EXRERNAL RTC (PD on X1, Apply 32KHz to RTC_CLK)	DISABLE PCI MEM BOOT

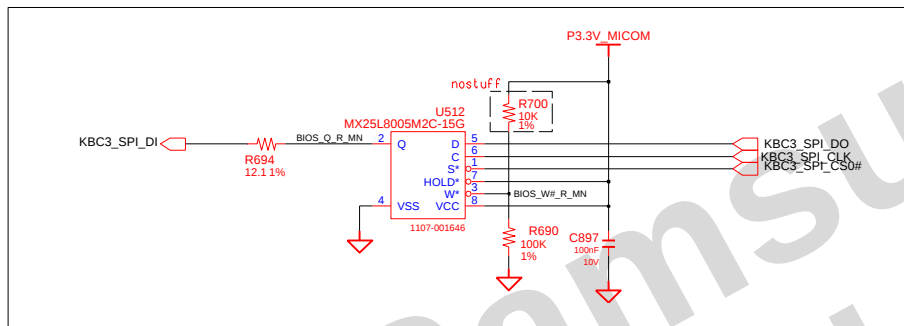


Remove SB_TEST pins for mass production. (For ASIC debug only - AMD)

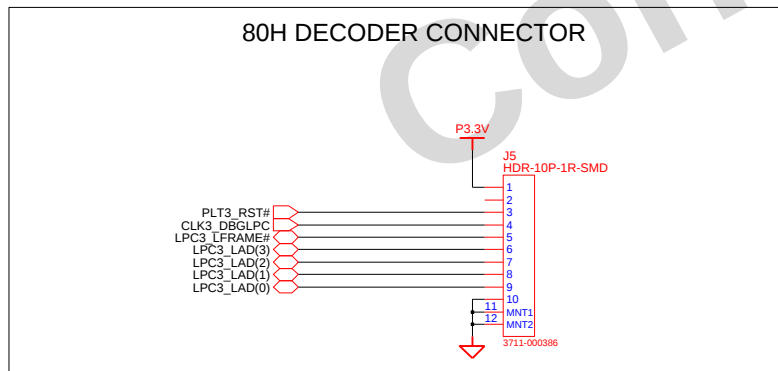
DRAW	H.J.Ra	DATE	9/23/2008	Bremen-D ICH SB710 STRAPS (5/5)		SAMSUNG ELECTRONICS			
CHECK	K.Y.Kim	DEV. STEP	ADV1						
APPROVAL	H.K.Park	REV	1.1						
				PART NO.		BA41-XXXXXA			
MODULE CODE		LAST EDIT		October 10, 2009 16:50:44 PM		PAGE	32	OF	61

SPI_BIOS_ROM

8MBit

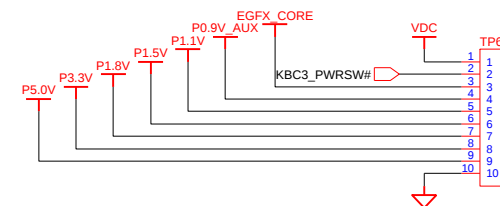


80H DECODER CONNECTOR



02 VERIFY REAL MODE
03 DISABLE NMI
04 GET CPU TYPE
05 INIT. SYSTEM H/W
06 INIT. CHIPSET REG.
07 SET IN POST FLAG
08 INIT CPU REG
09 CPU CACHE ON
10 INIT. CACHE TO POST
11 INIT. I/O VALUE
12 ENABLE THE L-BUS IDE
13 INIT. POWER MANAGER
14 LOAD ALTERNATE REG.
15 PCI BUS MASTER RESET
16 WITH INITIAL POST VALUE
17 INIT. KEYBOARD CONTROLLER
18 CHECK CHECKSUM
19 8254 TIMER INIT
20 8237 DMA CONTROLLER INIT
21 RESET INTERRUPT CONTROLLER
22 TEST DRAM REFRESH
23 TEST 8742 KEYBOARD CONTROLLER
24 SET ES SEGMENT REG. TO 4GB
25 ENABLE A20
26 AUTO SIZING DRAM
27 COMPUTE THE CPU SPEED
28 TEST CMOS RAM
29 SHADOW SYSTEM BIOS ROM
30 AUTO SIZING CACHE
31 CONFIGURE ADVANCED CHIPSET REG.
32 LOAD ALTERNATE REG. WITH CMOS VALUE
33 INIT. INTERRUPT VECTOR
34 INIT. BIOS INTERRUPT
35 CHECK ROM COPYRIGHT NOTICE
36 INIT. I20 SUPPORT IF INSTALLED
37 CHECK VIDEO CONFIGURE AGAINST CMOS
38 INIT. PCI BUS AND DEVICE
39 INIT. ALL VIDEO BIOS ROM
40 SHADOW VIDEO BIOS ROM
41 DISPLAY CPU TYPE AND SPEED
42 TEST KEYBOARD
43 SET KEYCLICK IF ENABLED
44 ENABLE KEYBOARD
45 TEST FOR UNEXPECTED INTERRUPTS
46 DISPLAY "PRESS SETUP"
47 TEST RAM BETWEEN 512K AND 640K
48 TEST EXTENDED MEMORY
49 TEST EXTENDED MEMORY ADDRESS LINE
50 JUMP TO USER PATCH 1
51
52
53
54
55
56
57
58
59
60
61
62
63
64
65
66 CONFIGURE ADVANCE CACHE REG.
67 DISPLAY EXTERNAL CACHE SIZE
68 DISPLAY SHADOW MESSAGE
69 DISPLAY NON-DISPOSABLE SEGMENT
70 DISPLAY ERROR MESSAGE
71 CHECK FOR CONFIGURATION ERROR
72 TEST REAL-TIME CLOCK
73 CHECK FOR KEYBOARD ERROR
74 SETUP HARDWARE INTERRUPT VECTOR
75 TEST COPROCESSOR IF PRESENT
76 DISABLE ON-BOARD I/O PORT
77 DETECT AND INSTALL EXT RS232C
78 DETECT AND INSTALL EXT PARALLEL
79 RE-INIT. ON-BOARD I/O PORT
80 INIT. BIOS DATA ROM
81 INIT. EXTENDED BIOS DATA AREA
82 INIT. FDD CONTROLLER
83 SHADOW OPTION ROMS
84 SETUP POWER MANAGEMENT
85 ENABLE H/W INTERRUPT
86 SET TIME OF DAY
87 INIT. TYPEMATIC RATE
88 ERASE F2 PROMPT
89 SCAN FOR F2 KEY STROKE
90 ENTER SETUP
91 CLEAR IN POST FLAG
92 CHECK FOR ERRORS
93 POST DONE-PREPARE TO BOOT O/S
94 ONE BEEP
95 CHECK PASSWORD (OPTION)
96 ACPI INIT
97 DMII INIT
98 CLEAR SCREEN
99 TRY BOOT WITH INT19
100 INTERRUPT HANDLER ERROR
101 UNKNOWN INTERRUPT ERROR
102 PENDING INTERRUPT ERROR
103 SHUTDOWN 5
104 SHUTDOWN ERROR
105 EXTENDED BLOCK MOVE
106 SHUTDOWN 10
107 ENABLE NMI
108 INIT. HDD CONTROLLER
109 INIT. LOCAL BUS HDD CONTROLLER
110 JUMP TO USER PATCH 2
111 DISABLE A20 ADDRESS LINE
112 CLEAR HUGE ES SEGMENT REG.
113 SEARCH FOR OPTION ROMS

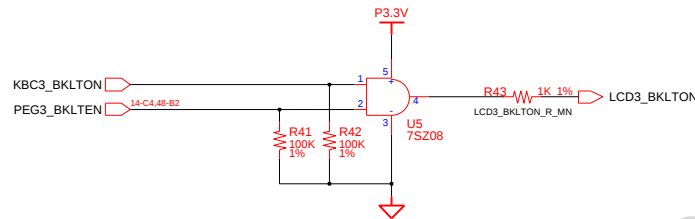
Pins for ICT FREE
should be rearranged.



DRAW	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D	SAMSUNG
CHECK	K.Y.Kim	DEV. STEP	ADV1		SPI_BIOS_ROM	ELECTRONICS
APPROVAL	H.K.Park	REV	1.1		SPI_BIOS_ROM	PART NO.
MODULE CODE		LAST EDIT				BA41-xxxxxA
October 10, 2009 16:50:44 PM						PAGE 33 OF 61

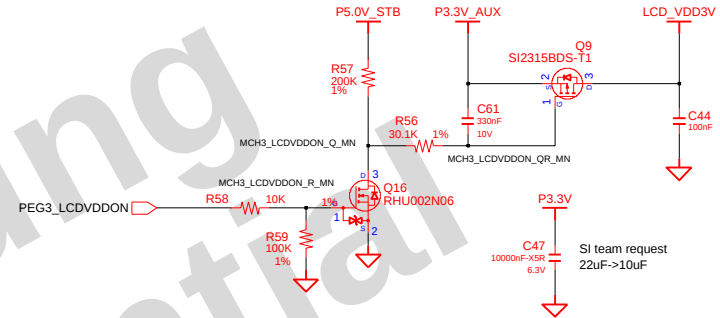
LVDS

Backlight On

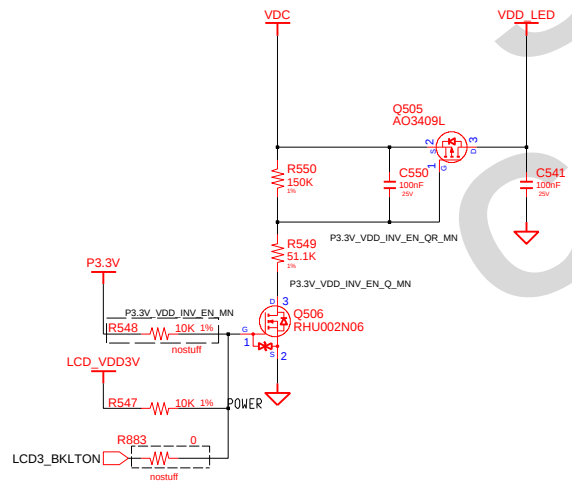


LCD Power

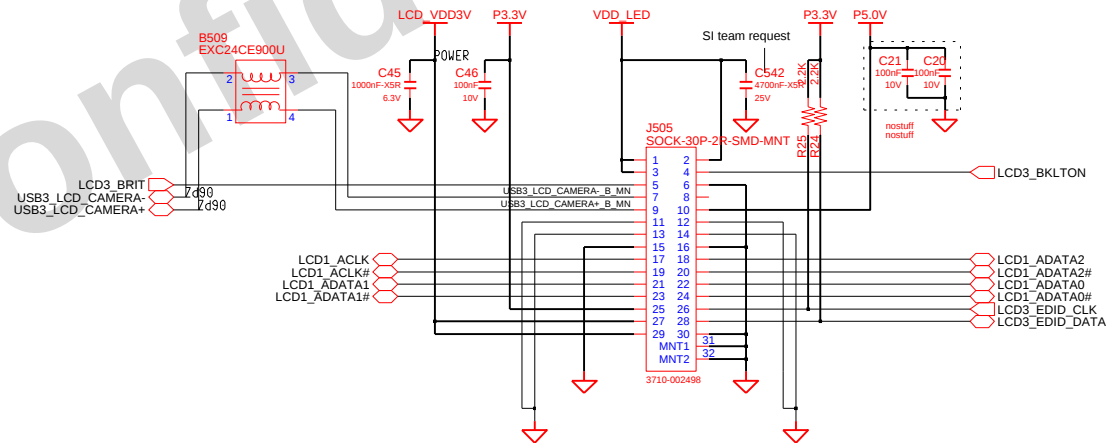
EBL Purpose



LED Power



Camera + LCD Connector



DESIGN	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D
CHECK	K.Y.Kim	DEV. STEP	ADV1	GRAPHICS_IF	
APPROVAL	H.K.Park	REV	1.1	LVDS	
MODULE CODE		LAST EDIT			
				October 10, 2009 16:50:44 PM	PAGE 34 OF 61

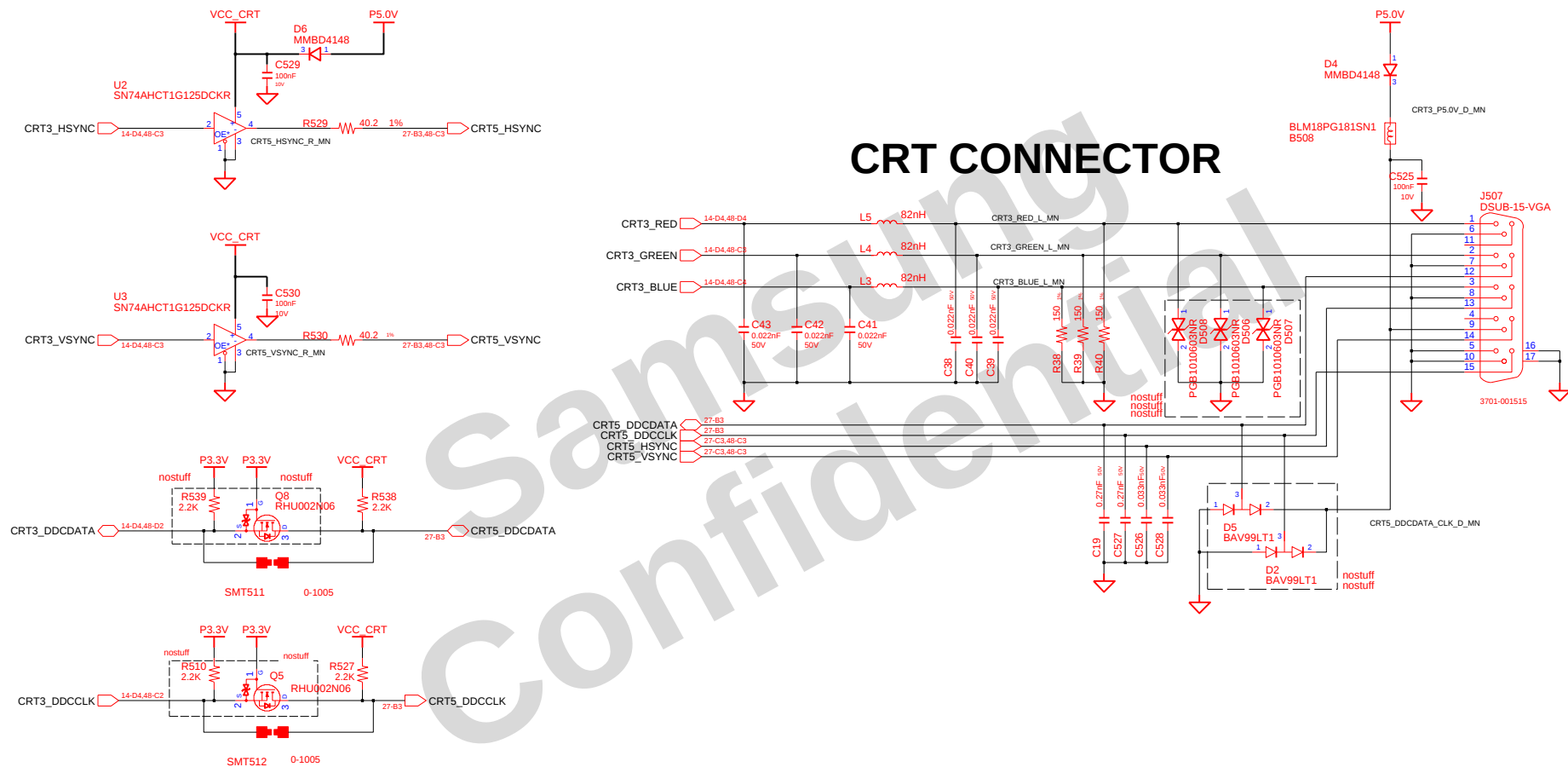
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CRT

CRT CONNECTOR



Check "CRT3_DDCCLK/DATA" Voltage Level
2N06 Can be replaced with SM6K2

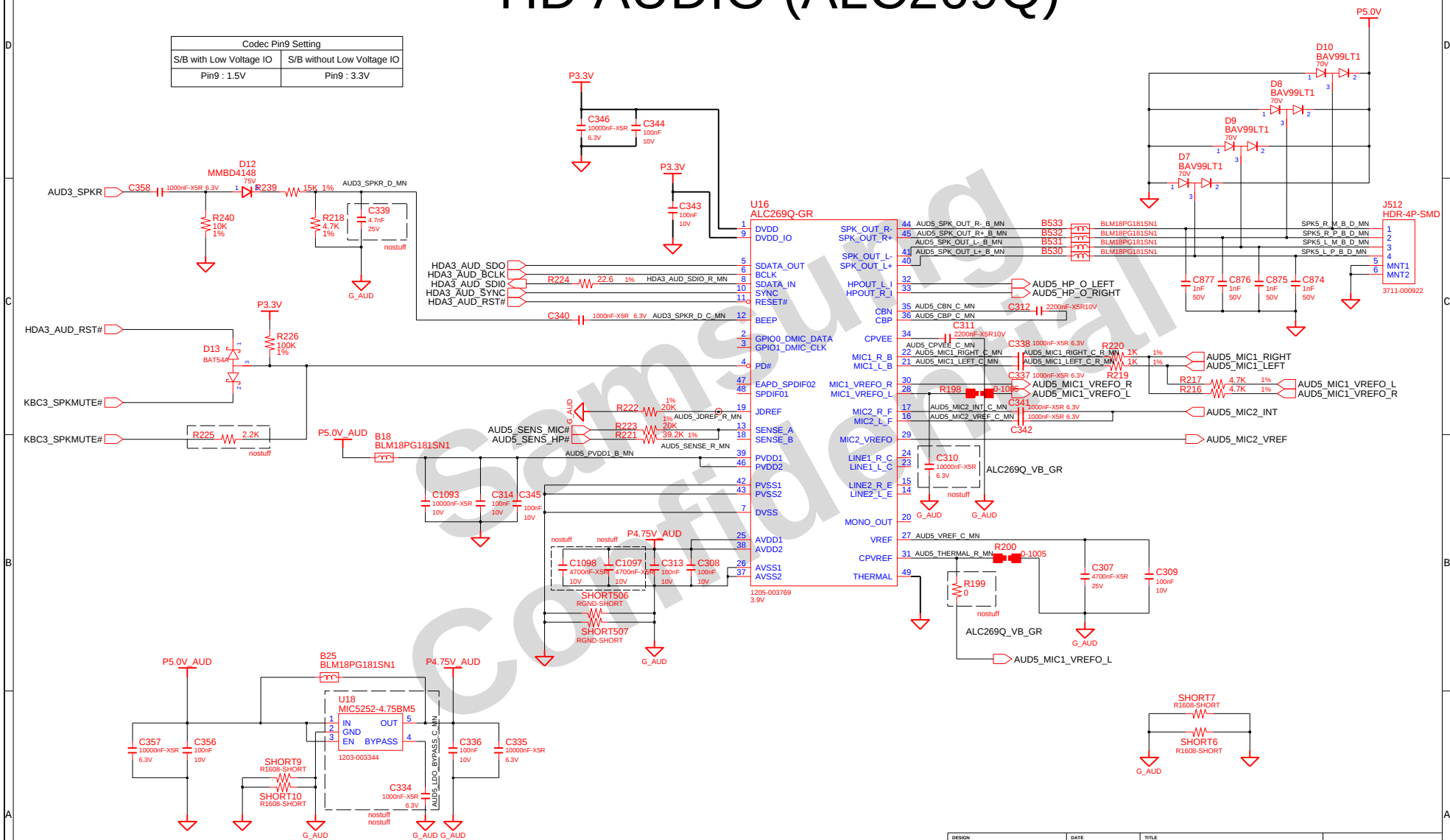
DESIGN	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D	SAMSUNG
CHECK	K.Y.Kim	DEV. STEP	ADV1	GRAPHICS_IF	ELECTRONICS	
APPROVAL	H.K.Park	REV	1.1	CRT		PART NO.
MODULE CODE		LAST EDIT				BA41-xxxxxA
				October 10, 2009 16:50:44 PM	PAGE	35 OF 61

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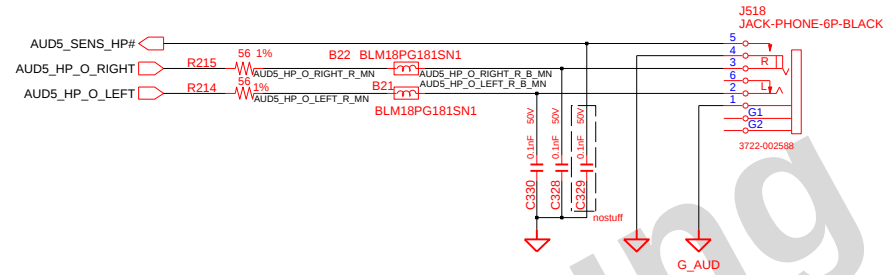
HD AUDIO (ALC269Q)

Codec Pin9 Setting	
S/B with Low Voltage IO	S/B without Low Voltage IO
Pin9 : 1.5V	Pin9 : 3.3V

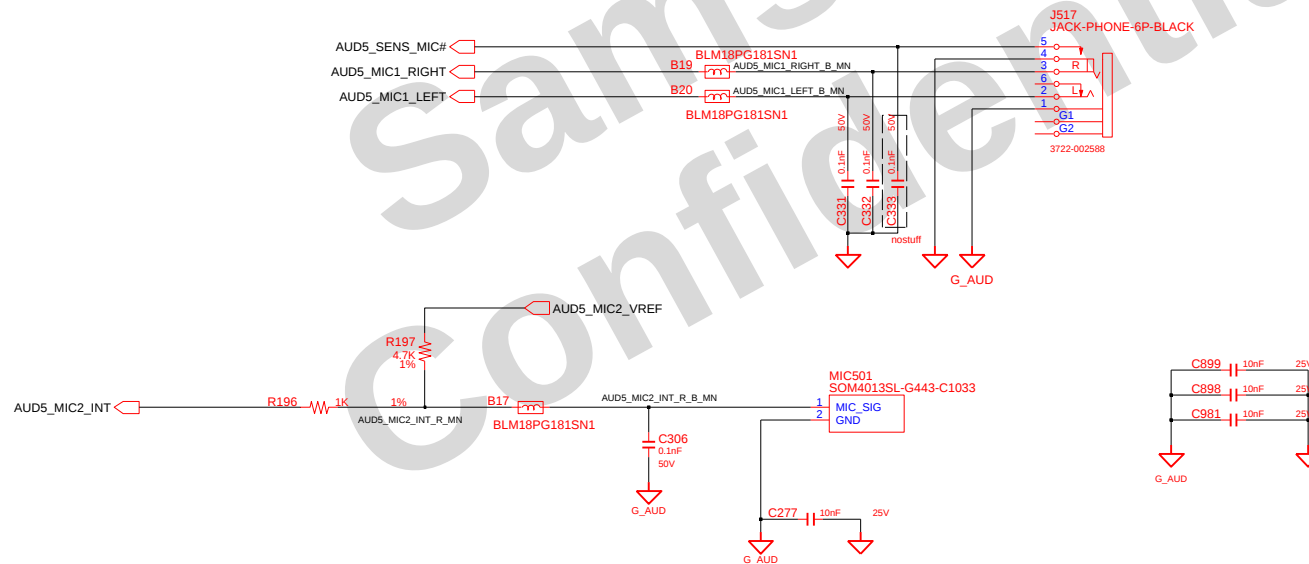


DESIGN	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D HDA_CODEC AUDIO CODEC ALC269Q_GR	SAMSUNG ELECTRONICS
CHECK	K.Y.Kim	DEV. STEP	ADV1			PART NO. BA41-xxxxxA
APPROVAL	H.K.Park	REV	1.1			
MODULE CODE		LAST EDIT				
				October 10, 2009 16:50:44 PM		
				PAGE	37	OF 61

HEADPHONE(BLACK)



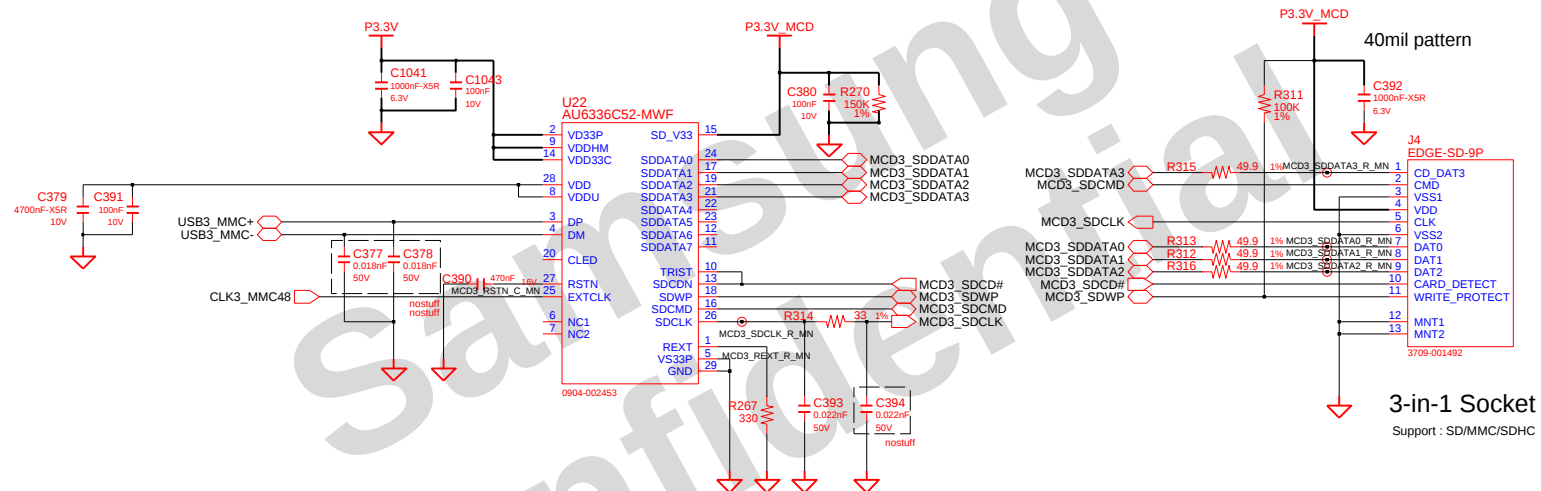
MIC JACK(BLACK)



DESIGN	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D	SAMSUNG ELECTRONICS
CHECK	K.Y.Kim	DEV. STEP	ADV1	HDA_CODEC		
APPROVAL	H.K.Park	REV	1.1	AUDIO INPUT/OUTPUT		
MODULE CODE		LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	38	OF 61

COM-22C-015(1996.6.5) REV. 3

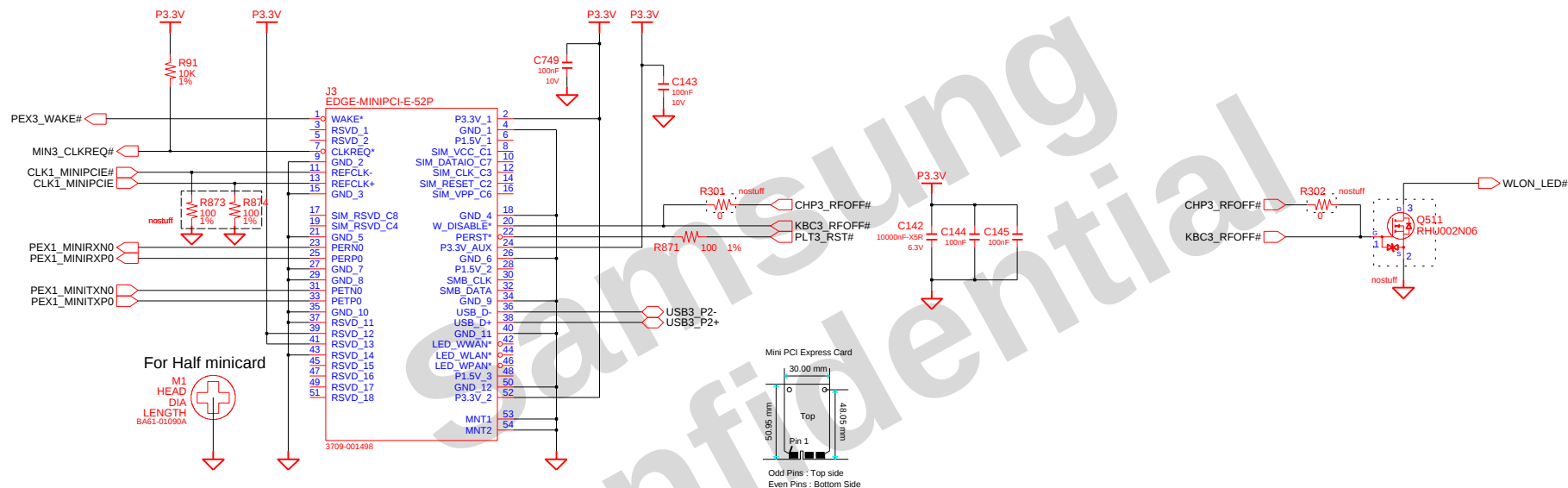
3 IN 1 CARD (AU6336)



DESIGN	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D	SAMSUNG ELECTRONICS
CHECK	K.Y.Kim	DEV. STEP	ADV1		MULTICARD	
APPROVAL	H.K.Park	REV	1.1		3 IN 1 CARD	
MODULE CODE		LAST EDIT		October 10, 2009 16:50:44 PM	PAGE 40 OF 61	PART NO. BA41-xxxxxA

Wireless LAN

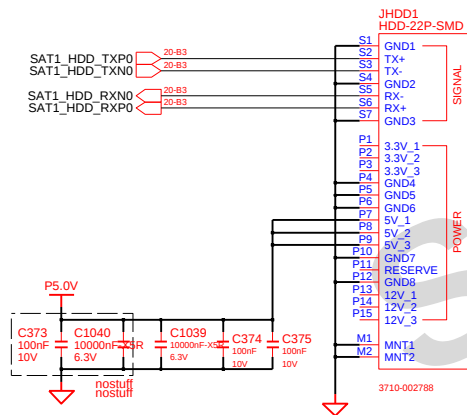
WLAN, 4mm



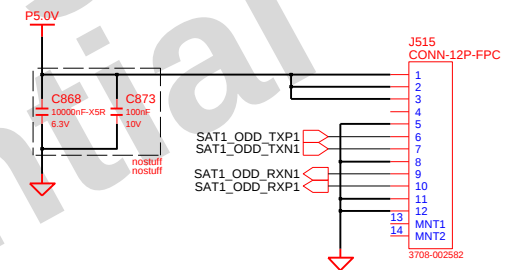
DESIGN	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D	SAMSUNG ELECTRONICS
CHECK	K.Y.Kim	DEV. STEP	ADV1	MINI_PCIE_CONN		
APPROVAL	H.K.Park	REV	1.1	WLAN		
MODULE CODE		LAST EDIT		October 10, 2009 16:50:44 PM	PAGE 41 OF 61	PART NO. BA41-xxxxxA

SATA I/F CONN

SATA HDD CONN



MAIN TO SUB SATA ODD CONN



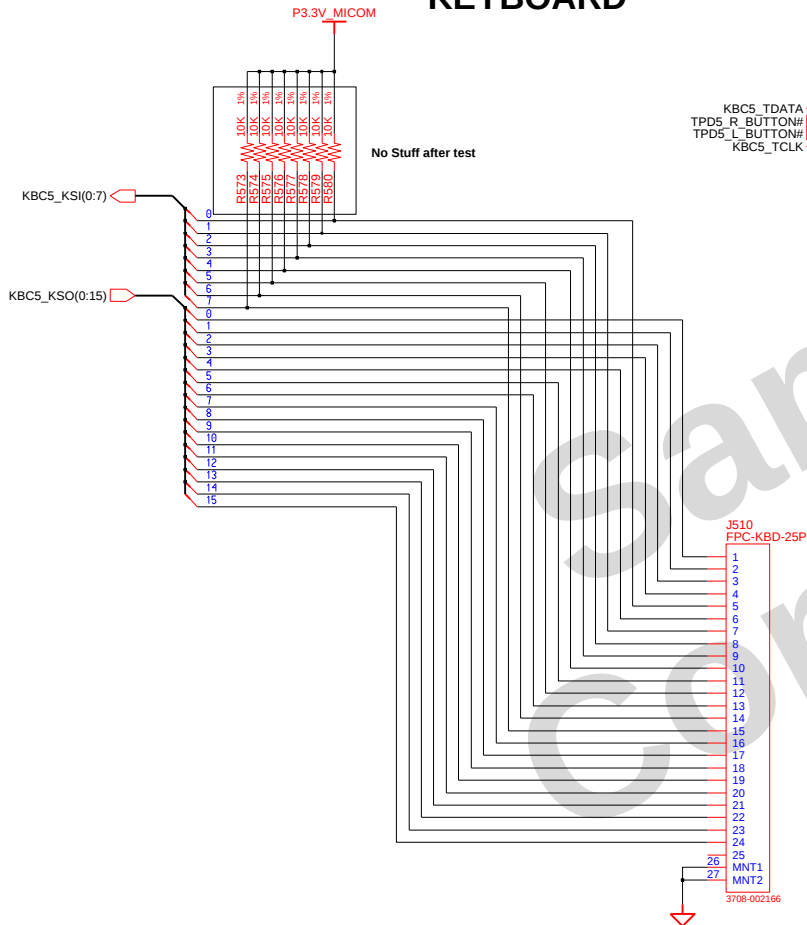
DESIGN	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D	SAMSUNG
CHECK	K.Y.Kim	DEV. STEP	ADV1		SATA_DEVICES	ELECTRONICS
APPROVAL	H.K.Park	REV	1.1		HDD & ODD SUB CONNECTOR	PART NO. BA41-xxxxxA
MODULE CODE		LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	42	OF 61



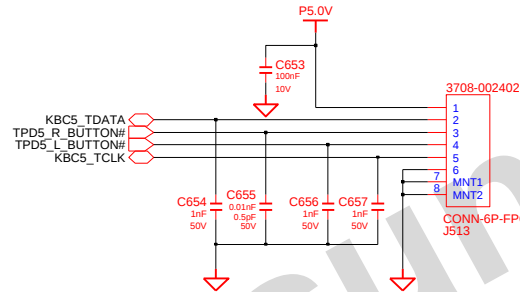
DRAW	H.J.Ra	DATE	9/23/2008	Bremen-D MICOM MICOM_SMSC MEC1308	SAMSUNG ELECTRONICS
CHECK	K.Y.Kim	DEV. STEP	ADV1		
APPROVAL	H.K.Park	REV	1.1		
MODULE CODE	LAST EDIT				
October 10, 2009 16:50:44 PM				PAGE	43
				OF	61

Micom Glue Logic

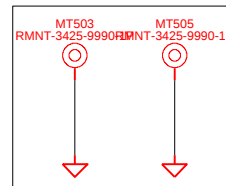
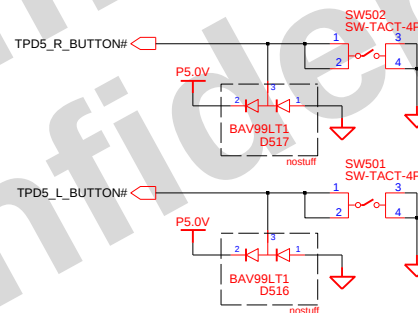
KEYBOARD



TOUCHPAD

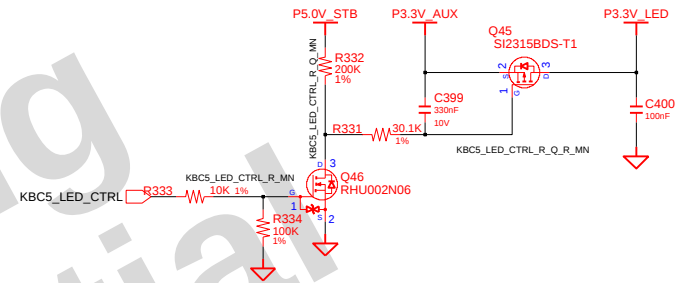


TOUCHPAD BUTTON

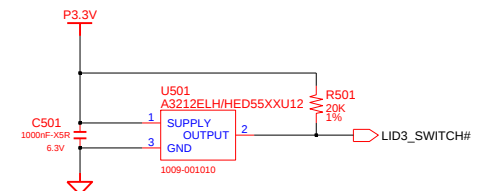


Keyboard Mount(for 15")

TOUCHPAD LED



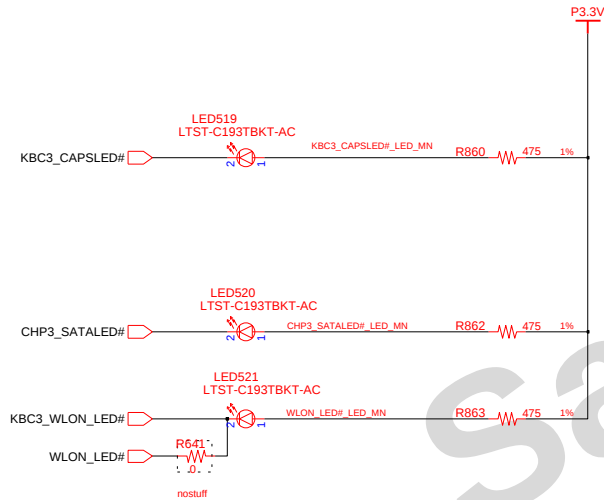
LID SWITCH



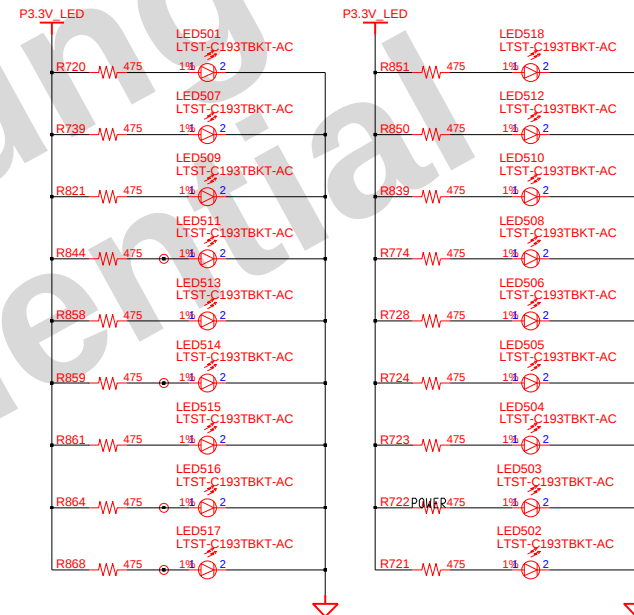
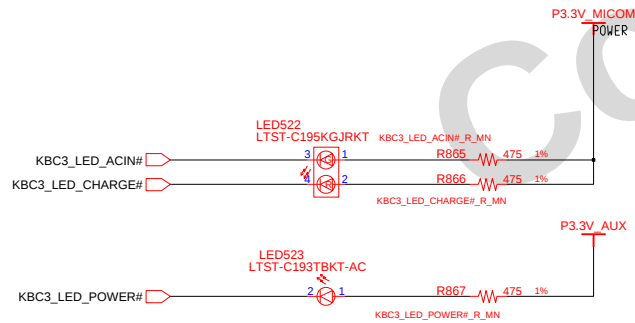
DESIGN	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D MICOM GLUE LOGIC KEYBOARD & TOUCHPAD	SAMSUNG ELECTRONICS
CHECK	K.Y.Kim	DEV. STEP	ADV1			PART NO. BA41-xxxxxA
APPROVAL	H.K.Park	REV	1.1			
MODULE CODE		LAST EDIT		October 10, 2009 16:50:44 PM	PAGE 44 OF 61	

LEDs

FUNCTION KEY LED

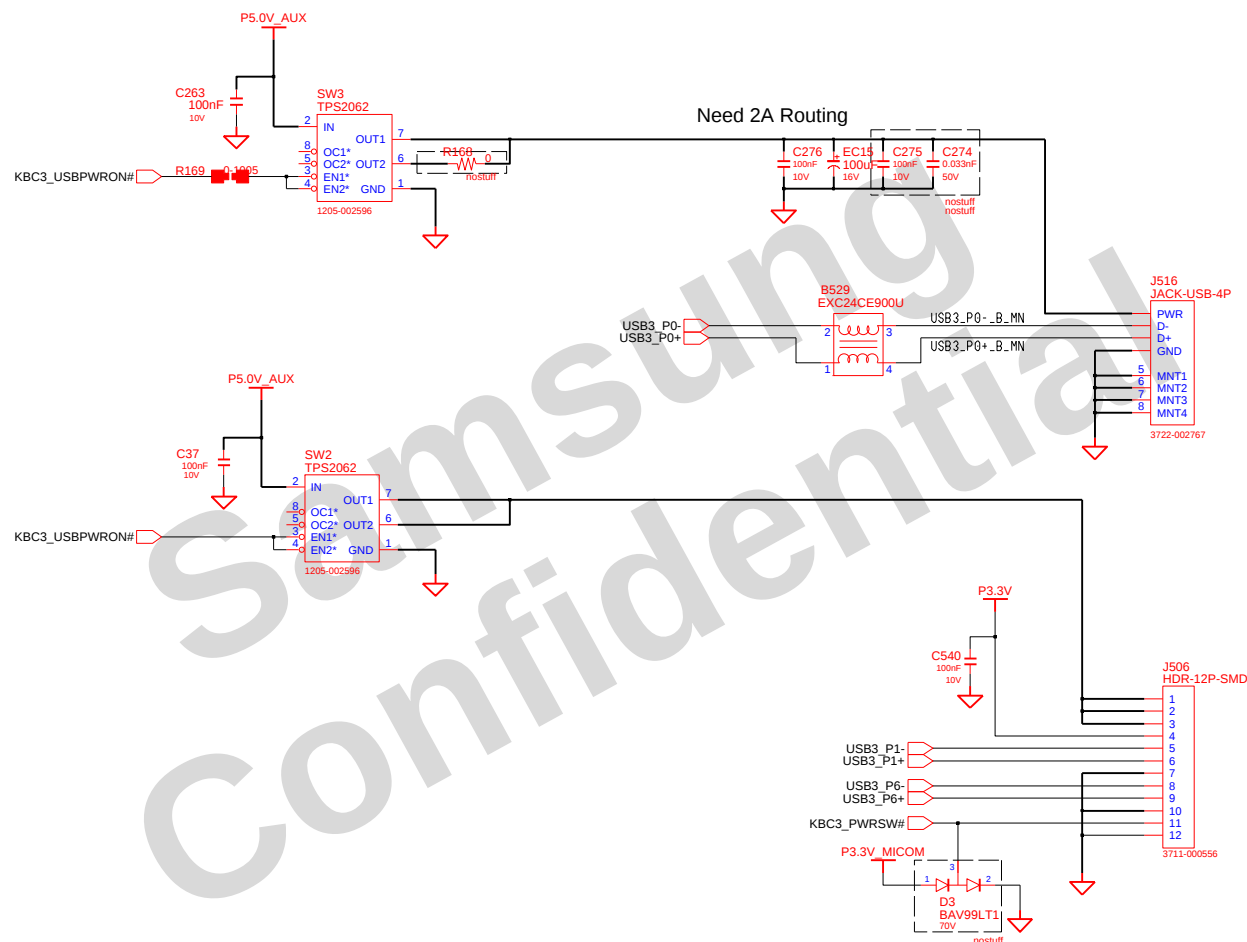


ADAPTERIN/CHARGING LED



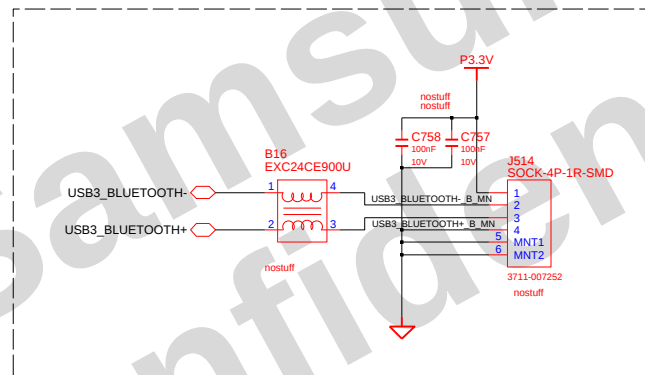
DRAW	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D	SAMSUNG
CHECK	K.Y.Kim	DEV. STEP	ADV1	LED_SWITCH	LED_SWITCH	ELECTRONICS
APPROVAL	H.K.Park	REV	1.1	LED_SWITCH	PART NO.	BA41-xxxxxA
MODULE CODE	LAST EDIT		October 10, 2009 16:50:44 PM		PAGE	45 OF 61

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DESIGN	H.J.Ra	DATE	9/23/2008	Bremen-D USB_CONN USB	SAMSUNG ELECTRONICS			
CHECK	K.Y.Kim	DEV. STEP	ADV1		PART NO.	BA41-XXXXXA		
APPROVAL	H.K.Park	REV	1.1					
MODULE CODE	LAST EDIT							
				October 10, 2009 16:50:44 PM	PAGE	46	OF	61

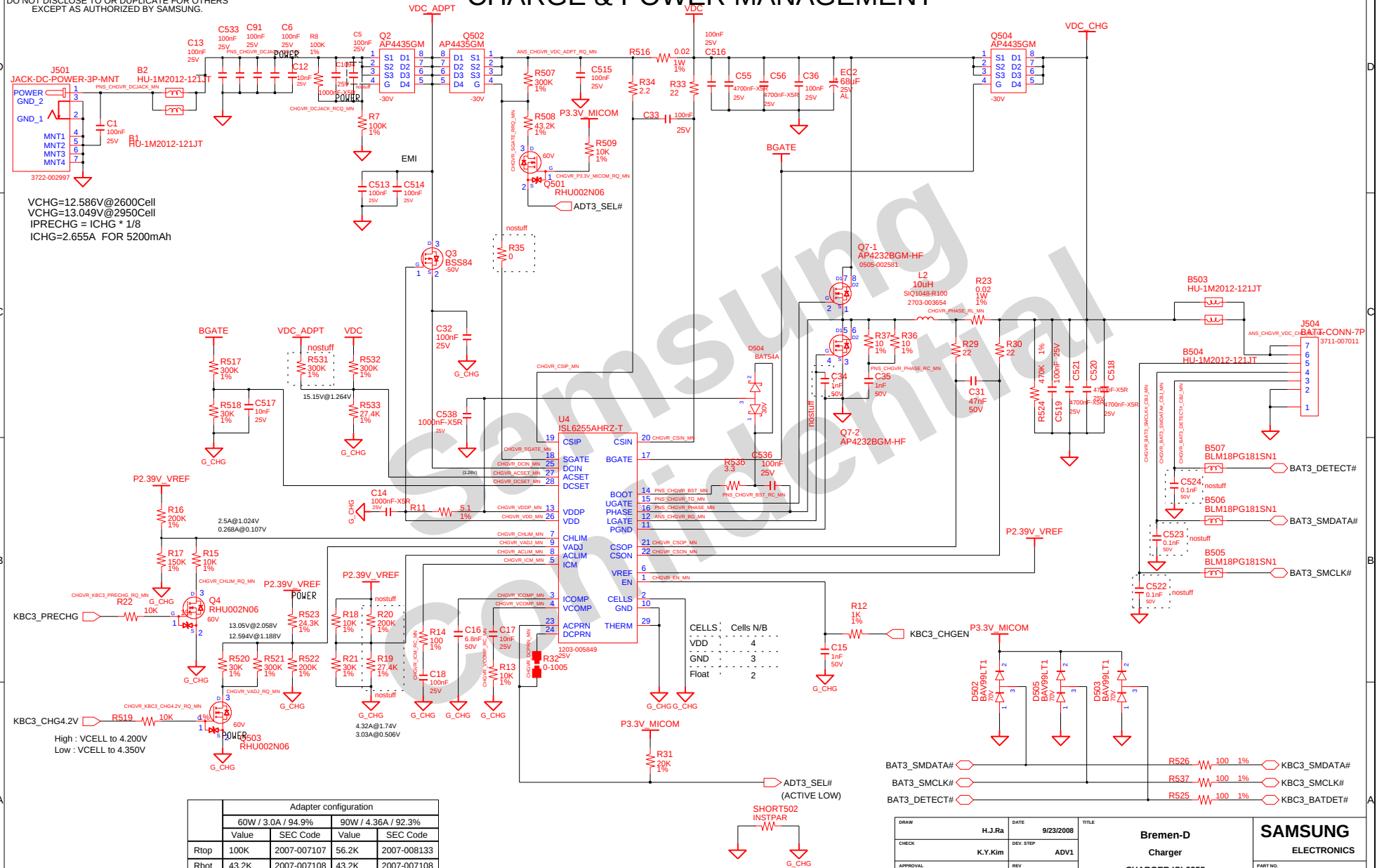
Bluetooth Interface



COM-22C-015(1996.6.5) REV. 3

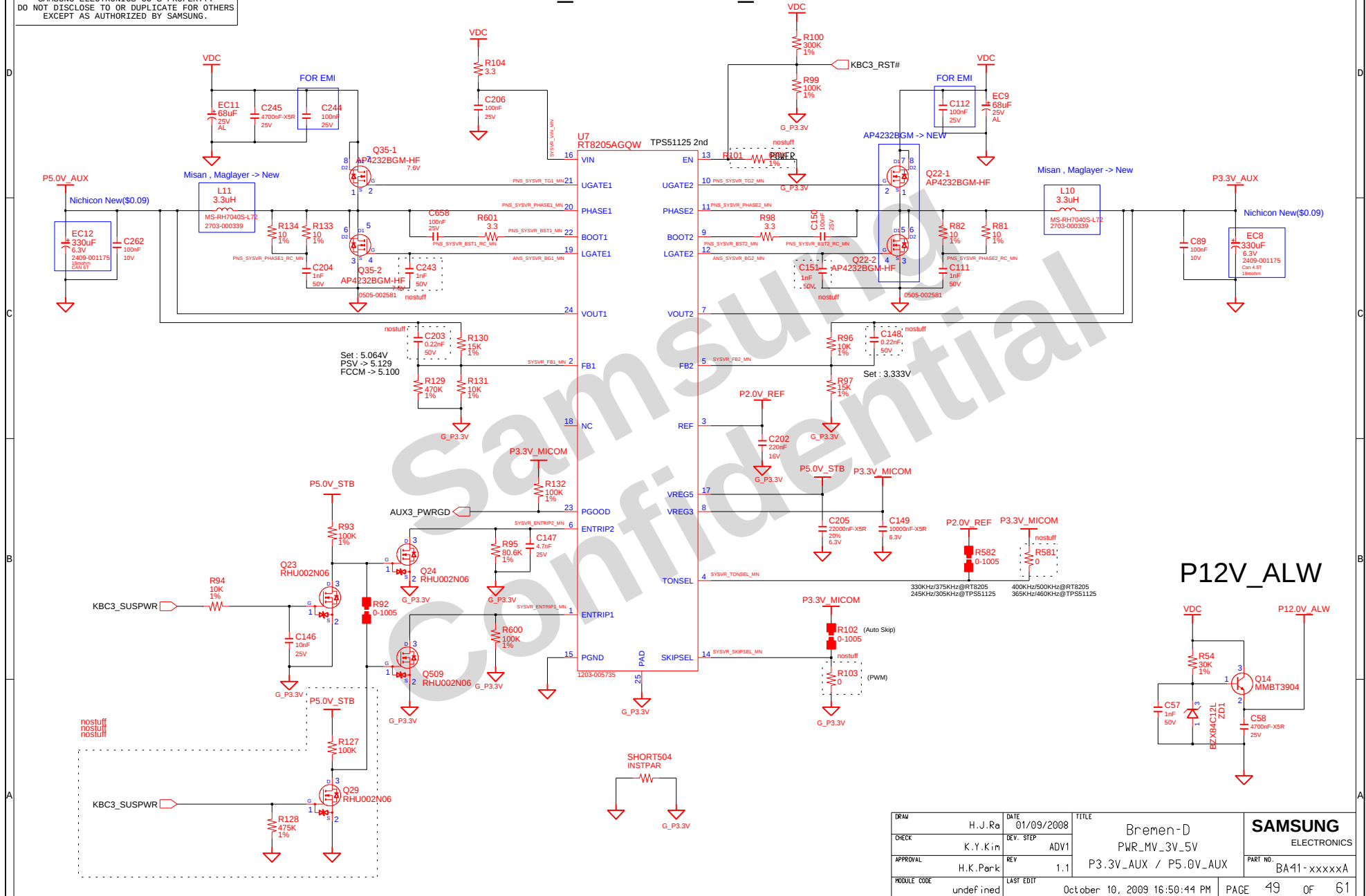
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CHARGE & POWER MANAGEMENT



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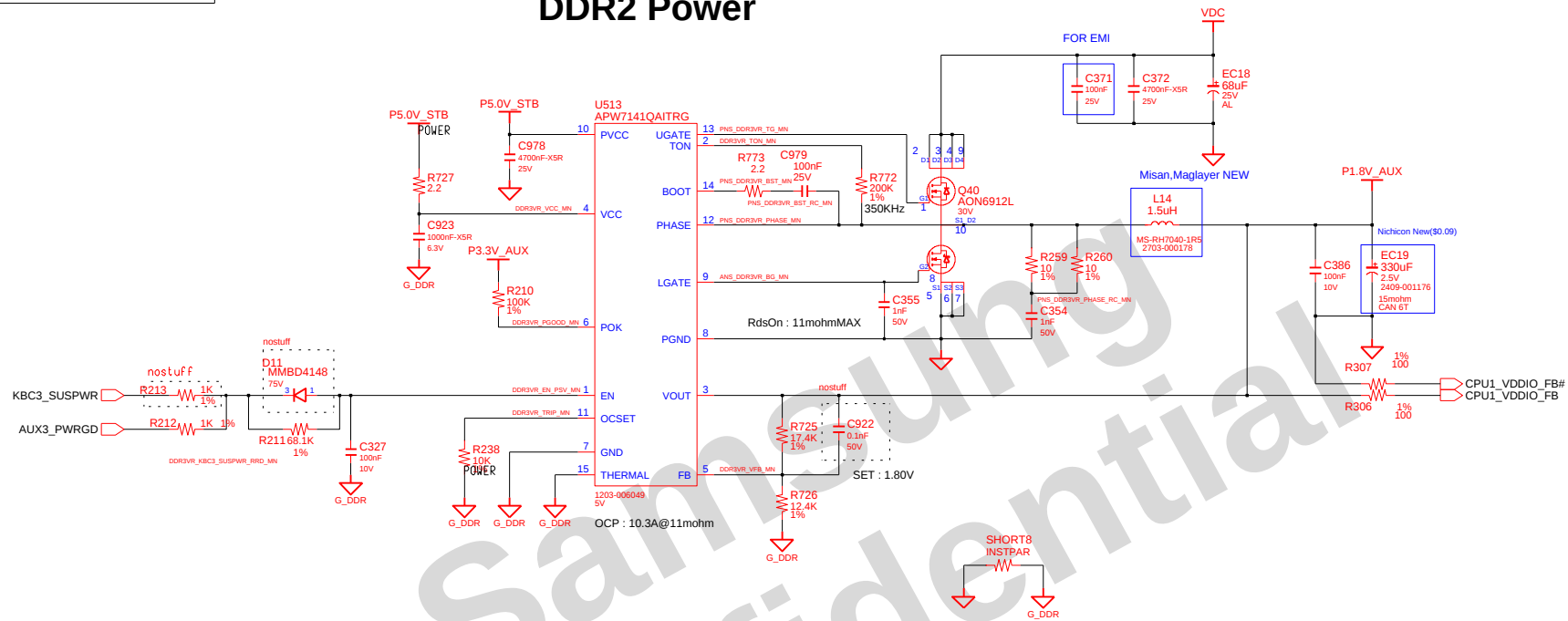
P3.3V_AUX & P5.0V_AUX



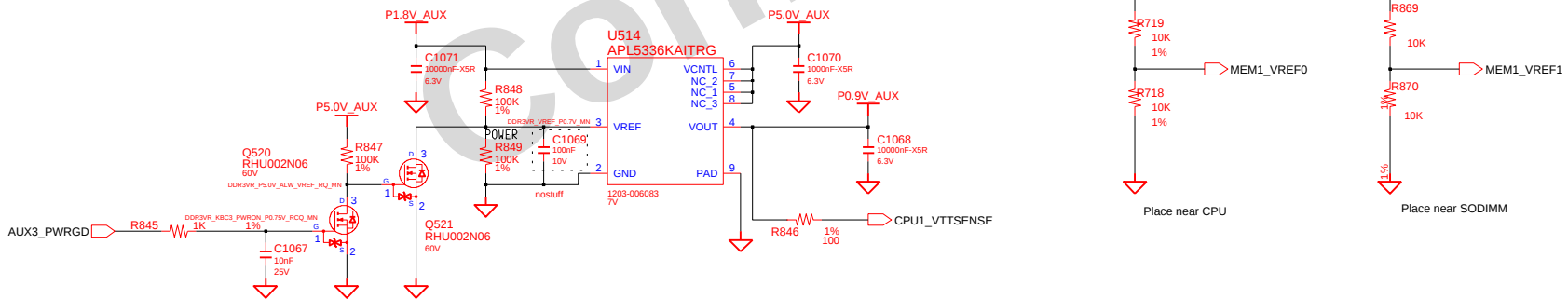
DRAW	H.J.Ro	DATE	01/09/2008	TITLE	Bremen-D	SAMSUNG
CHECK	K.Y.Kim	DEV. STEP	ADV1	PWR_MV_3V_5V		ELECTRONICS
APPROVAL	H.K.Park	REV	1.1	P3.3V_AUX / P5.0V_AUX	PART NO.	BA41-xxxxxA
MODULE CODE	undefined	LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	49	OF 61

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DDR2 Power



DDR2 VTT(0.9V_AUX)

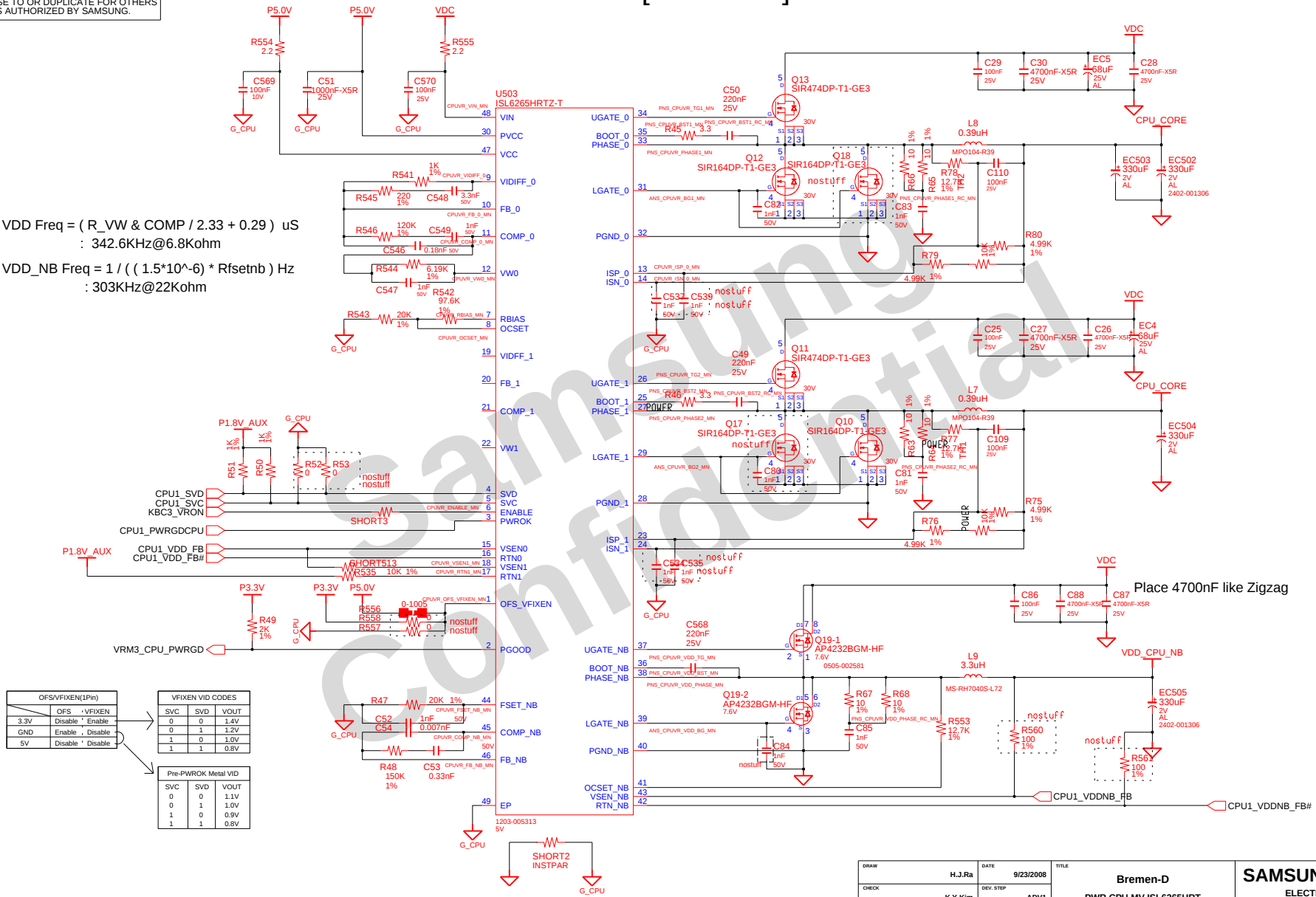


DRAW	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D	SAMSUNG
CHECK	K.Y.Kim	DEV. STEP	ADV1	PWR_MEMORY	DDR2 POWER	ELECTRONICS
APPROVAL	H.K.Park	REV	1.1			PART NO.
MODULE CODE	undefined	LAST EDIT	October 10, 2009 16:50:44 PM			BA41-xxxxxA
				PAGE	50	OF 61

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CPU VRM [INTERSIL]

$VDD \text{ Freq} = (R_VW \& COMP / 2.33 + 0.29) \mu S$
: 342.6KHz@6.8Kohm
 $VDD_NB \text{ Freq} = 1 / ((1.5 \times 10^{-6}) * Rfsetnb) \text{ Hz}$
: 303KHz@22Kohm



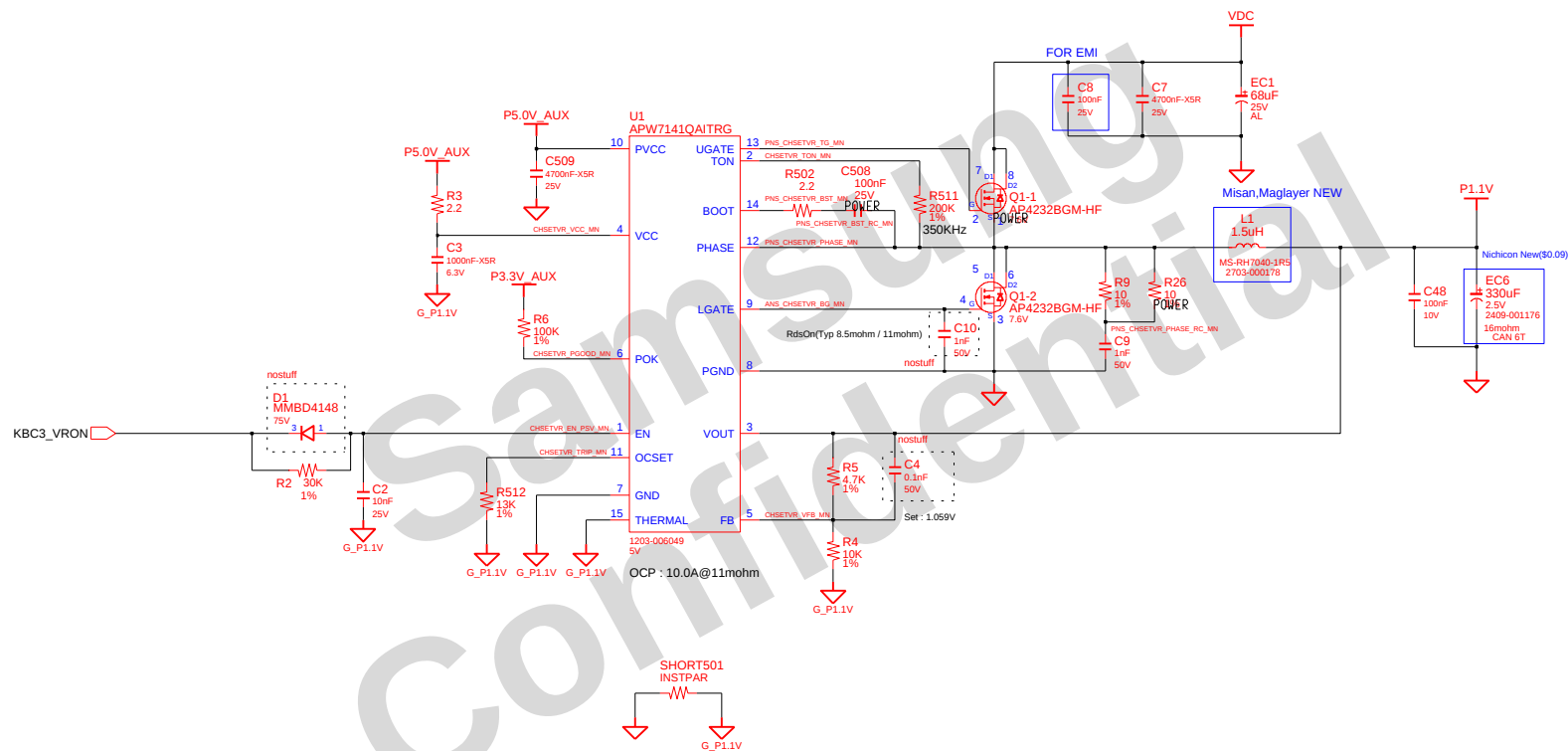
OFS/VFIXEN(1Pin)		VFIXEN VID CODES		
SVC	SVD	VOUT		
3.3V	Disable	Enable	0	0
GND	Enable	Disable	0	1
5V	Disable	Disable	1	0
			1	1

Pre-PWROK Metal VID		
SVC	SVD	VOUT
0	0	1.1V
0	1	1.0V
1	0	0.9V
1	1	0.8V

DRAW	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D
CHECK	K.Y.Kim	DEV. STEP	ADV1		PWR CPU MV ISL6265HRT
APPROVAL	H.K.Park	REV	1.1		CPU VRM
MODULE CODE	undefined	LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	51 OF 61

SAMSUNG
ELECTRONICS
PART NO.
BA41-xxxxxA

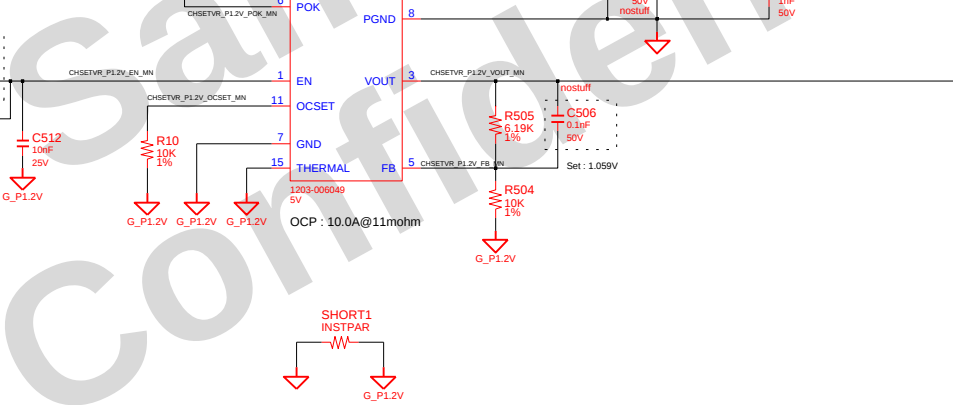
CHIPSET POWER(P1.1V)



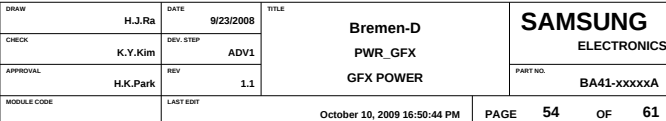
DESIGN	H.J.Ro	DATE	9/3/2009	TITLE	Bremen-D PWR MV RX881 P1.1V	SAMSUNG ELECTRONICS PART NO. BA41-xxxxxA
CHECK	K.Y.Kim	DEV. STEP	ADV1			
APPROVAL	H.K.Park	REV	1.1			
MODULE CODE		LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	52 OF 61	

A

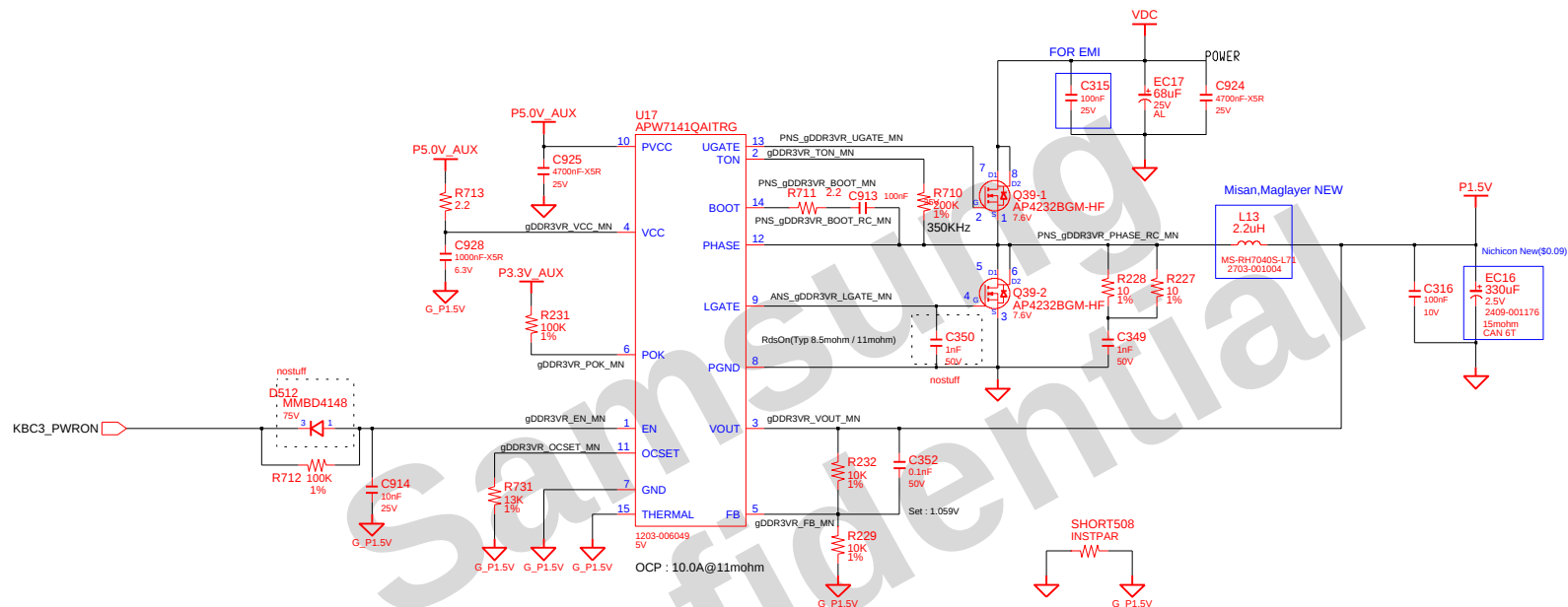
A



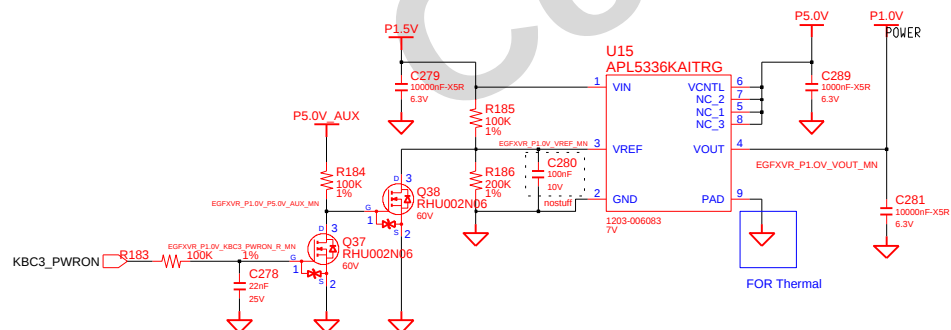
COM-22C-015(1996.6.5) REV. 3



gDDR3 POWER(P1.5V)



P1.0V

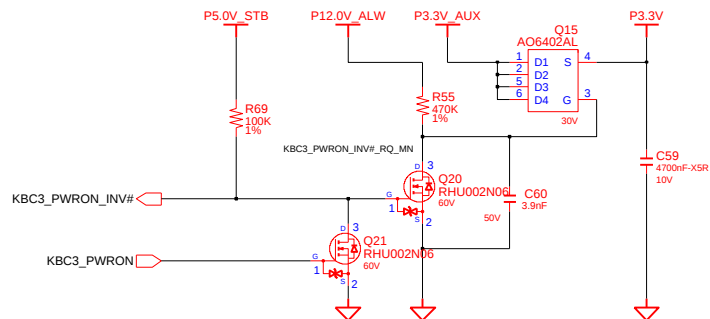


DRAW	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D	SAMSUNG
CHECK	K.Y.Kim	DEV. STEP	ADV1	PWR GFX MEMORY	ELECTRONICS	
APPROVAL	H.K.Park	REV	1.1	gDDR3 POWER	PART NO.	BA41-xxxxxA
MODULE CODE	undefined	LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	55	OF 61

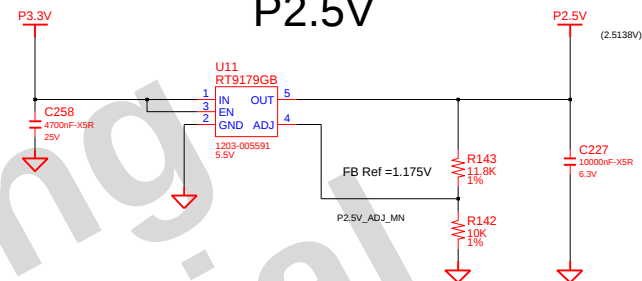
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Switched Power

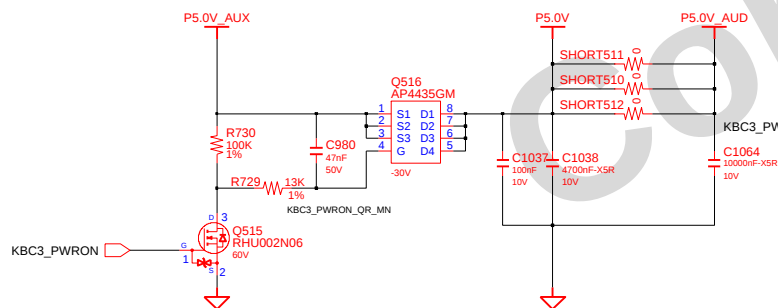
Switched Power On (P3.3V)



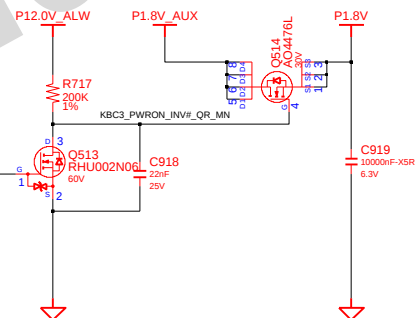
P2.5V



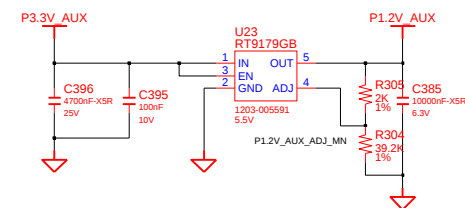
Switched Power On (P5.0V)



Switched Power On (P1.8V)



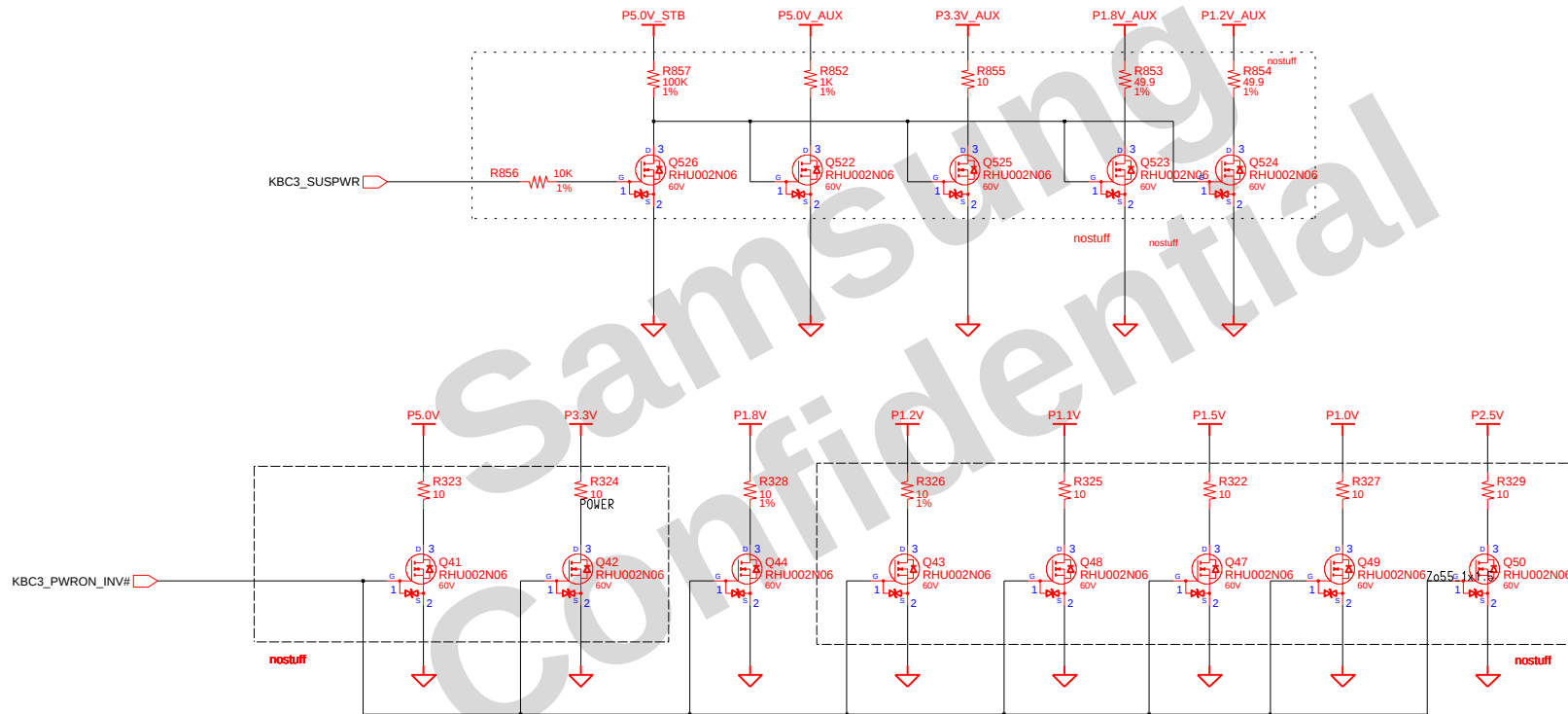
P1.2V_AUX



DESIGN	H.J.Ro	DATE	8/22/2009	TITLE	Bremen-D PWR_MV_SWITCHED SWITCHED POWER	SAMSUNG ELECTRONICS
CHECK	K.Y.Kim	DEV. STEP	ADV1			PART NO. BA41-xxxxxA
APPROVAL	H.K.Park	REV	1.1			
MODULE CODE		LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	56	OF 61

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POWER DISCHARGER

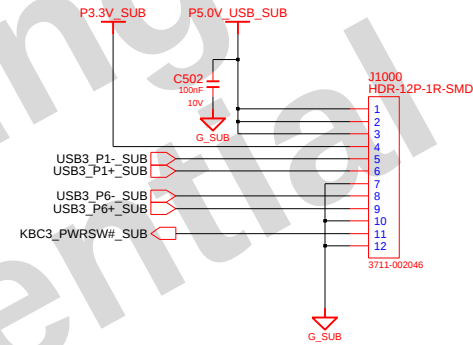
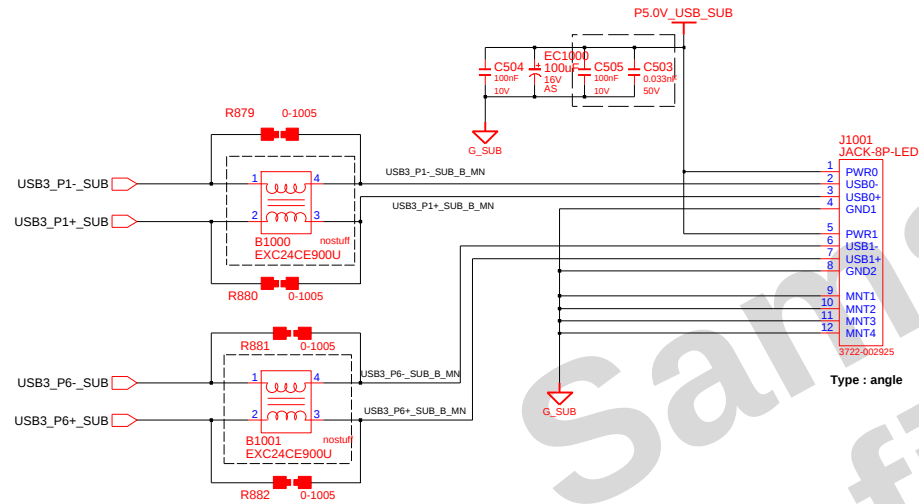


DRAW	H.J.Ra	DATE	9/23/2008	TITLE Bremen-D PWR_MV_DISCHARGER DISCHARGER LOGIC	SAMSUNG ELECTRONICS PART NO. BA41-XXXXXA
CHECK	K.Y.Kim	DEV. STEP	ADV1		
APPROVAL	H.K.Park	REV	1.1		
MODULE CODE	undefined	LAST EDIT	October 10, 2009 16:50:44 PM		PAGE 57 OF 61

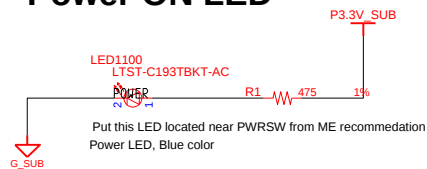
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2 USB PORT & POWER S/W SUB B'D

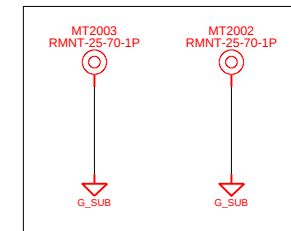
SUB TO MAIN USB CONN



Power ON LED



Power Button

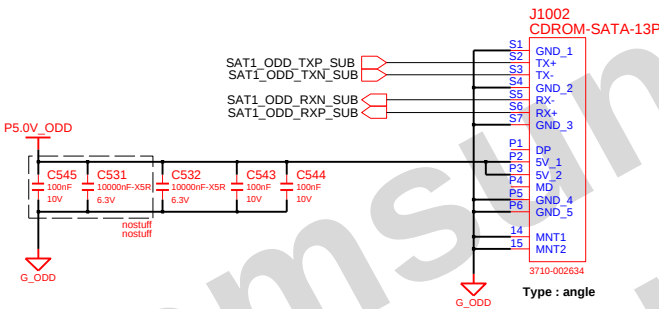


USB sub board mount hole

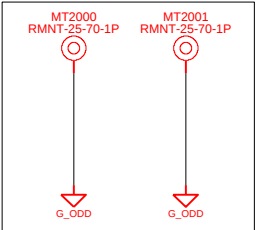
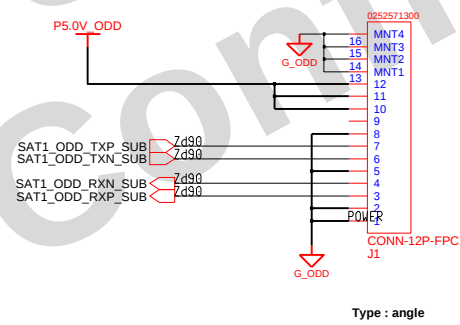
DRAW	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D SUB BOARD1	SAMSUNG ELECTRONICS
CHECK	K.Y.Kim	DEV. STEP	ADV1			
APPROVAL	H.K.Park	REV	1.1	USB PORT, POWER SW SUB BOARD	PART NO.	BA41-xxxxxA
MODULE CODE		LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	58	OF 61

SATA ODD SUBBOARD

SATA ODD CONN



SUB TO MAIN SATA ODD CONN

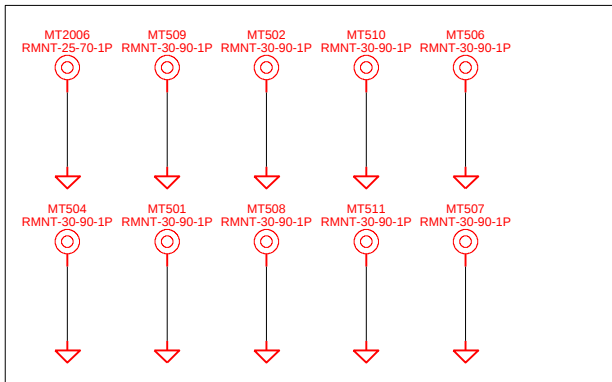


ODD sub board mount hole

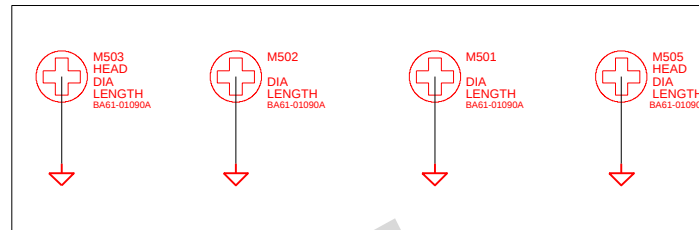
DRAW	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D SUB BOARD2 SATA ODD SUB BOARD	SAMSUNG ELECTRONICS
CHECK	K.Y.Kim	DEV. STEP	ADV1			PART NO. BA41-xxxxxA
APPROVAL	H.K.Park	REV	1.1			
MODULE CODE	undefined	LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	59	OF 61

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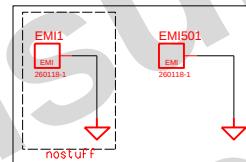
Mainboard Mount



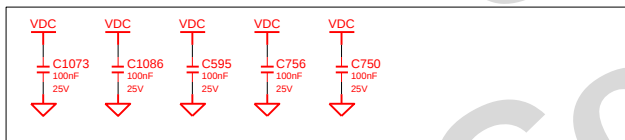
(30,90) x 7, (25,70) x 1



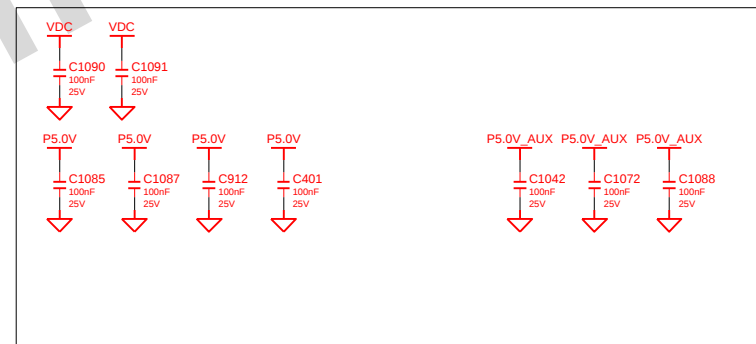
To Support Heatsink



EMI Finger



Add for EMC (Bottom)



Add for EMC (Bottom)

DRAW	H.J.Ra	DATE	9/23/2008	TITLE	Bremen-D MAIN MOUNT HOLE	SAMSUNG ELECTRONICS
CHECK	K.Y.Kim	DEV. STEP	ADV1			PART NO. BA41-xxxxxA
APPROVAL	H.K.Park	REV	1.1			
MODULE CODE		LAST EDIT	October 10, 2009 16:50:44 PM	PAGE	60	OF 61

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CPU1_LDTRDE#
CPU1_ALL_LD1STP
CPU1_LDTRST#
CPU1_LD1STP#
CPU1_PROCHOT#
CPU1_PWRGDCEP
CPU1_SIC
CPU1_SIO
CPU1_SVC
CPU1_SVD
CPU1_THMRTRIP#
CPU1_VDDIO_FB
CPU1_VDDIO_FB#
CPU1_VDDNB_FB
CPU1_VDDNB_FB#
CPU1_VDD_FB
CPU1_VDD_FB#
CPU1_VTSENSE
CPUVR_COMP_0_MN
CPUVR_COMP_NB_MN
CPUVR_ENABLE_MN
CPUVR_FB_0_MN
CPUVR_FB_NB_MN
CPUVR_FSET_NB_MN
CPUVR_ISET_0_MN
CPUVR_OCSET_MN
CPUVR_OFS_VFIXEN_MN
CPUVR_RBIAS_MN
CPUVR_RIM_MN
CPUVR_VDIFF_0
CPUVR_VIN_MN
CPUVR_VSEN1_MN
CPUVR_VW_0_MN
CPU_VDDA0_R_MN
CPU_VDDA1_B_MN
CRT3_BLUE
CRT3_BLUE_L_MN
CRT3_DDCCLK
CRT3_DDCDATA
CRT3_GREEN
CRT3_GREEN_L_MN
CRT3_HSYNC
CRT3_P5_OV_D_MN
CRT3_RED
CRT3_RED_L_MN
CRT3_VSYNC
CRT3_DDCCLK
CRT3_DDCDATA
CRT3_DDCDATA_CLK_D_MN
CRT5_HSYNC_R_MN
CRT5_HSYNC_R_MN
DDR3V3_KBC3_PWRON_0_75V_RQD_MN
DDR3V3_KBC3_SUSPWR_RD0_MN
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DDR3V3_PGOOD_MN
DDR3V3_VREF_0_MN
DDR3V3_TRIP_MN
DDR3V3_VCC_MN
DDR3V3_VFB_MN
EGF_XVR_NB_MN
EGF_XVR_P1_MN
EGF_XVR_P1_OV_KBC3_PWRON_R_MN
EGF_XVR_P1_OV_P5_OV_AUX_MN
EGF_XVR_P1_OV_VOUT_MN
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GDDR3VR_TSD_136_MN
GDDR3VR_TSD_137_MN
GDDR3VR_TSD_138_MN
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GDDR3VR_TSD_242_MN
GDDR3VR_TSD_243_MN
GDDR3VR_TSD_244_MN
GDDR3VR_TSD_245_MN
GDDR3VR_TSD_246_MN
GDDR3VR_TSD_2

KBC3_PFOFF#
KBC3_RSMRST#
KBC3_RST#
KBC3_RUNSC#
KBC3_SMCLK#
KBC3_SMDATA#
KBC3_SPT_CLK
KBC3_SPT_CSO#
KBC3_SPT_DI
KBC3_SPT_DO
KBC3_SPMUTE#
KBC3_SUSPWR
KBC3_THERM_SMCLK
KBC3_THERM_SMDATA
KBC3_USBPWRON#
KBC3_VRON
KBC3_WAKESC#
KBC3_WLONLED#
KC05_KST(0)
KC05_KST(1)
KC05_KST(2)
KC05_KST(3)
KC05_KST(4)
KC05_KST(5)
KC05_KST(6)
KC05_KST(7)
KC05_KS0(0)
KC05_KS0(1)
KC05_KS0(10)
KC05_KS0(11)
KC05_KS0(12)
KC05_KS0(13)
KC05_KS0(14)
KC05_KS0(15)
KC05_KS0(2)
KC05_KS0(3)
KC05_KS0(4)
KC05_KS0(5)
KC05_KS0(6)
KC05_KS0(7)
KC05_KS0(8)
KC05_KS0(9)
KC05_LED_CTRL
KC05_LED_CTRL_R_Q_MN
KC05_LED_CTRL_R_Q_R_MN
KC05_TDATA
LTD3_SWITCH#
LPC3_CLK0
LPC3_CLK1
LPC3_LD(0)
LPC3_LD(1)
LPC3_LD(2)
LPC3_LD(3)
LPC3_RAME#
MCD3_SDCD0
MCD3_SDCLK
MCD3_SDCMD
MCD3_SDDATA0
MCD3_SDDATA1
MCD3_SDDATA2
MCD3_SDDATA3
MCD3_SDPW
MC03_EXT10#
MC03_EXT15#
MEMO_SAO_R_MN
MEMO_SAI_R_MN
MEM_CALRNL
MEM_CALRNL_R_MN
MEM_OPI_VDD15_NC_R_MN
NB_KBC3_PWRGD_Q_MN
NB_PCE_CALRNP_PCE_BCALRN_R_MN
NB_PCE_CALRNP_PCE_BCALRP_R_MN
NB_SYSPRESET_R_MN
NB_TESTMODE_R_MN
NB_VDDA18HTPL_L_B_MN
NB_VDDA18PCEPLL_B_MN
NB_VDDA18_P_ADJ_MN
P2_5V0_ADU

OSB_USB_RCOMP_R_MN
OSB_WAKE#_EVENT8#_R_MN
VRM3_CPU_PWRGD
SMB3_ALERT#
SMB3_CLK
SMB3_DATA#
SP13_CLK
SP13_CS0
SP13_MISO
SP13_MOSI
SYSVR_ENTRIP1_MN
SYSVR_ENTRIP2_MN
SYSVR_FB1_MN
SYSVR_FB2_MN
SYSVR_TSEL_MN
SYSVR_TONSEL_MN
SYSVR_VIN_MN
IHM3_ALERT#
IHM3_STP#
XHC1_CSPDSQ_MN
I2H_SHDN_SEL_R_MN
I2H_TRIP_SEL_R_MN
I2H_VDD_3V_R_MN
P05_BUTTON#
P05_R_BUTTON#
P1_8V_VDD01
P1_8V_VDD01
PGATE
PGATE
CPU_CORE
CPU_CORE
CG_AUD
CG_AUD
CG_CHG
CG_CHG
VCC_CRT
VDC_ADPT
VDC_ADPT
VDC_CHG
VDC_CHG
VDD_CPU_NB
VDD_CPU_NB
CG_CPU
CG_CPU
CG_DDR
CG_DDR
CG_EFX
CG_EFX
CG_P1_1V
CG_P1_1V
CG_P1_2V
CG_P1_2V
CG_P1_5V
CG_P3_3V
CG_P3_3V
LCD_VDD3V
LCD_VDD3V
PG_9V_AUX
PG_9V_AUX
P1_2V_AUX
P1_2V_AUX
P1_2V_AUX
P1_2V_AUX
P1_2V_AUX
P1_2V_AUX
P1_8V_A2VDD0
P1_8V_A2VDD0
P1_8V_AUX
P1_8V_AUX
P12_0V_ALW
P12_0V_ALW
P2_0V_REF
P2_33V_VREF
P2_33V_VREF
P2_5V
P2_5V
P2_5V_LAN
P2_5V_LAN
P3_3V_A2VDD
P3_3V_A2VDD
P3_3V_A2VDD

- ☐ OP3.3V_AUX
- ☐ OP3.3V_AUX
- ☐ OP3.3V_LED
- ☐ OP3.3V_LED
- ☐ OP3.3V_MCD
- ☐ OP3.3V_MCD
- ☐ OP3.3V_MICOM
- ☐ OP3.3V_MICOM
- ☐ OP4.75V_AUD
- ☐ OP4.75V_AUD
- ☐ OP5.0V_AUD
- ☐ OP5.0V_AUD
- ☐ OP5.0V_AUX
- ☐ OP5.0V_AUX
- ☐ OP5.0V_STB
- ☐ OP5.0V_STB
- ☐ PRTC_BAT
- ☐ VCC-CRT
- ☐ VDD_LED